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(54) Title: SEMICONDUCTOR LIGHT EMITTING DEVICE MOUNTING SUBSTRATES AND PACKAGES INCLUDING CAVITIES AND COVER PLATES, AND METHODS OF PACKAGING SAME

(57) Abstract: A mounting substrate for a semiconductor light emitting device includes a solid metal block having first and second opposing metal faces. The first metal face includes a cavity that is configured to mount at least one semiconductor light emitting device therein, and to reflect light that is emitted by at least one semiconductor light emitting device that is mounted therein away from the cavity. One or more semiconductor light emitting devices are mounted in the cavity. A cap having an aperture is configured to matingly attach to the solid metal block adjacent the first metal face such that the aperture is aligned to the cavity. Reflective coatings, conductive traces, insulating layers, pedestals, through holes, lenses, flexible films, optical elements, phosphor, integrated circuits, optical coupling media, recesses and/or meniscus control regions also may be provided in the package. Related packaging methods also may be provided.



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**SEMICONDUCTOR LIGHT EMITTING DEVICE MOUNTING
SUBSTRATES AND PACKAGES INCLUDING CAVITIES AND COVER
PLATES, AND METHODS OF PACKAGING SAME**

Field of the Invention

This invention relates to semiconductor light emitting devices and manufacturing methods therefor, and more particularly to packaging and packaging methods for semiconductor light emitting devices.

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Background of the Invention

Semiconductor light emitting devices, such as Light Emitting Diodes (LEDs) or laser diodes, are widely used for many applications. As is well known to those having skill in the art, a semiconductor light emitting device includes one or more semiconductor layers that are configured to emit coherent and/or incoherent light upon energization thereof. It is also known that the semiconductor light emitting device generally is packaged to provide external electrical connections, heat sinking, lenses or waveguides, environmental protection and/or other functions.

For example, it is known to provide a two-piece package for a semiconductor light emitting device, wherein the semiconductor light emitting device is mounted on a substrate that comprises alumina, aluminum nitride and/or other materials, which include electrical traces thereon, to provide external connections for the semiconductor light emitting device. A second substrate which may comprise silver plated copper, is mounted on the first substrate, for example using glue, surrounding the semiconductor light emitting device. A lens may be placed on the second substrate over the semiconductor light emitting device. Light emitting diodes with two-piece packages as described above are described in Application Serial No. US 2004/0041222 A1 to Loh, entitled *Power Surface Mount Light Emitting Die Package*, published March 4, 2004, assigned to the assignee of the present invention, the disclosure of which is hereby incorporated herein by reference in its entirety as if set forth fully herein.

Summary of the Invention

Some embodiments of the present invention provide a mounting substrate for a semiconductor light emitting device that includes a solid metal block having first and second opposing metal faces. The first metal face includes therein a cavity that is
5 configured to mount at least one semiconductor light emitting device therein and to reflect light that is emitted by at least one semiconductor light emitting device that is mounted therein away from the cavity. The mounting substrate also includes a cap having an aperture that extends therethrough. The cap is configured to matingly attach to the solid metal block adjacent the first metal face, such that the aperture is
10 aligned to the cavity. In some embodiments, the second metal face includes therein a plurality of heat sink fins.

In some embodiments, a reflective coating is provided in the cavity and in the aperture. In other embodiments, a first conductive trace is provided on the first metal face and a second conductive trace is provided in the cavity that are configured to
15 connect to at least one semiconductor light emitting device that is mounted in the cavity. In some embodiments, the aperture includes therein a recess that is configured to expose the first conductive trace on the first face. In yet other embodiments, an insulating layer is provided on the first metal face, and a conductive layer is provided on the insulating layer that is patterned to provide the reflective coating in the cavity
20 and the first and second conductive traces. The solid metal block can be a solid aluminum block with an aluminum oxide insulating layer. In other embodiments, the solid metal block is a solid steel block with a ceramic insulating layer.

In still other embodiments of the invention, the first metal face includes a pedestal therein, and the cavity is in the pedestal. In yet other embodiments, the solid
25 metal block includes a through hole therein that extends from the first face to the second face. The through hole includes a conductive via therein that is electrically connected to the first or second conductive traces.

In some embodiments of the present invention, a semiconductor light emitting device is mounted in the cavity. In other embodiments, a lens extends across the
30 cavity. In still other embodiments, when the cavity is in a pedestal, the lens extends across the pedestal and across the cavity. In still other embodiments, a flexible film that includes an optical element therein is provided on the first metal face, wherein the optical element extends across the cavity or extends across the pedestal and across the cavity. Accordingly, semiconductor light emitting device packages may be provided.

Phosphor also may also be provided according to various elements of the present invention. In some embodiments, a coating including phosphor is provided on the inner and/or outer surface of the lens or optical element. In other embodiments, the lens or optical element includes phosphor dispersed therein. In yet other
5 embodiments, a phosphor coating is provided on the semiconductor light emitting device itself. Combinations of these embodiments also may be provided.

An integrated circuit also may be provided on the solid metal block that is electrically connected to the first and second traces. The integrated circuit may be a light emitting device driver integrated circuit.

10 An optical coupling medium may be provided in the cavity and in the aperture. Moreover, in some embodiments, the cover plate includes at least one meniscus control region therein that is configured to control a meniscus of the optical coupling media in the cavity.

Other embodiments of the present invention provide a mounting substrate for
15 an array of semiconductor light emitting devices. In these embodiments, the first metal face includes therein a plurality of cavities, a respective one of which is configured to mount at least one semiconductor light emitting device therein, and to reflect light that is emitted by the at least one semiconductor light emitting device that is mounted therein away from the respective cavity. The second metal face may
20 include a plurality of heat sink fins. A reflective coating, conductive traces, an insulating layer, pedestals, through holes, lenses, flexible films, optical elements, phosphor, integrated circuits and/or optical coupling media also may be provided according to any of the embodiments that were described above, to provide semiconductor light emitting device packages. Moreover, the cavities may be
25 uniformly and/or nonuniformly spaced apart from one another in the first face. A cap including therein a plurality of apertures that extend therethrough is also provided. The cap is configured to matingly attach to the solid metal block adjacent the first metal face, such that a respective aperture is aligned to a respective cavity. Recesses and/or meniscus control regions also may be provided according to any of the
30 embodiments that were described above.

Semiconductor light emitting devices may be packaged according to some embodiments of the present invention by fabricating a solid metal block including one or more cavities in a first face thereof, forming an insulating layer on the first face, forming a conductive layer and mounting a semiconductor light emitting device in at

least one of the cavities. A cap is matingly attached to the solid metal block adjacent the first metal face. The cap includes a plurality of apertures that extend therethrough, such that a respective aperture is aligned to a respective cavity. Pedestals, through holes, lenses, flexible films, optical elements, phosphor, integrated circuits, optical coupling media, recesses and/or meniscus control regions may be provided according to any of the embodiments that were described above.

Brief Description of the Drawings

Figures 1A-1H are side cross-sectional views of mounting substrates for semiconductor light emitting devices according to various embodiments of the present invention.

Figure 2 is a flowchart of steps that may be performed to fabricate mounting substrates for semiconductor light emitting devices according to various embodiments of the present invention.

Figures 3A and 3B are top and bottom perspective views of a semiconductor light emitting device package according to various embodiments of the present invention.

Figure 4 is an exploded perspective view of a packaged semiconductor light emitting device according to various embodiments of the present invention.

Figure 5 is an assembled perspective view of a packaged semiconductor light emitting device according to various embodiments of the present invention.

Figures 6A-6H are cross-sectional views of transmissive optical elements according to various embodiments of the present invention that may be used with semiconductor light emitting devices.

Figure 7 is a cross-sectional view of a semiconductor light emitting device package according to other embodiments of the present invention.

Figure 8 is a schematic diagram of a molding apparatus that may be used to fabricate optical elements according to embodiments of the present invention.

Figures 9 and 10 are flowcharts of steps that may be performed to package semiconductor light emitting devices according to various embodiments of the present invention.

Figures 11A and 11B, 12A and 12B, and 13A and 13B are cross-sectional views of semiconductor light emitting device packages during intermediate fabrication steps according to various embodiments of the present invention.

Figure 14 is an exploded cross-sectional view of a semiconductor light emitting device package and fabrication methods therefor, according to various embodiments of the present invention.

5 Figures 15-25 are cross-sectional views of semiconductor light emitting device packages according to various embodiments of the present invention.

Figure 26 is a perspective view of a semiconductor light emitting device package according to various embodiments of the present invention.

Figure 27 is a side cross-sectional view of a packaged semiconductor light emitting device according to various embodiments of the present invention.

10 Figure 28 is a perspective view of Figure 27.

Figure 29 is a side cross-sectional view of a packaged semiconductor light emitting device according to other embodiments of the present invention.

Figure 30 is a flowchart of steps that may be performed to package semiconductor light emitting devices according to various embodiments of the present invention.

Figure 31 is a side cross-sectional view of mounting substrates for semiconductor light emitting devices according to various embodiments of the present invention.

20 Figure 32 is a side cross-sectional view of a packaged semiconductor light emitting device according to various embodiments of the present invention.

Detailed Description

The present invention now will be described more fully hereinafter with reference to the accompanying drawings, in which embodiments of the invention are shown. However, this invention should not be construed as limited to the
25 embodiments set forth herein. Rather, these embodiments are provided so that this disclosure will be thorough and complete, and will fully convey the scope of the invention to those skilled in the art. In the drawings, the thickness of layers and regions are exaggerated for clarity. Like numbers refer to like elements throughout.
30 As used herein the term "and/or" includes any and all combinations of one or more of the associated listed items and may be abbreviated as "/".

The terminology used herein is for the purpose of describing particular embodiments only and is not intended to be limiting of the invention. As used herein, the singular forms "a", "an" and "the" are intended to include the plural forms as well,

unless the context clearly indicates otherwise. It will be further understood that the terms "comprises" and/or "comprising," when used in this specification, specify the presence of stated features, regions, steps, operations, elements, and/or components, but do not preclude the presence or addition of one or more other features, regions, steps, operations, elements, components, and/or groups thereof.

It will be understood that when an element such as a layer or region is referred to as being "on" or extending "onto" another element, it can be directly on or extend directly onto the other element or intervening elements may also be present. In contrast, when an element is referred to as being "directly on" or extending "directly onto" another element, there are no intervening elements present. It will also be understood that when an element is referred to as being "connected" or "coupled" to another element, it can be directly connected or coupled to the other element or intervening elements may be present. In contrast, when an element is referred to as being "directly connected" or "directly coupled" to another element, there are no intervening elements present.

It will be understood that, although the terms first, second, etc. may be used herein to describe various elements, components, regions, layers and/or sections, these elements, components, regions, layers and/or sections should not be limited by these terms. These terms are only used to distinguish one element, component, region, layer or section from another region, layer or section. Thus, a first element, component, region, layer or section discussed below could be termed a second element, component, region, layer or section without departing from the teachings of the present invention.

Furthermore, relative terms, such as "lower", "base", or "horizontal", and "upper", "top", or "vertical" may be used herein to describe one element's relationship to another element as illustrated in the Figures. It will be understood that relative terms are intended to encompass different orientations of the device in addition to the orientation depicted in the Figures. For example, if the device in the Figures is turned over, elements described as being on the "lower" side of other elements would then be oriented on "upper" sides of the other elements. The exemplary term "lower", can therefore, encompasses both an orientation of "lower" and "upper," depending on the particular orientation of the figure. Similarly, if the device in one of the figures is turned over, elements described as "below" or "beneath" other elements would then be

oriented "above" the other elements. The exemplary terms "below" or "beneath" can, therefore, encompass both an orientation of above and below.

Embodiments of the present invention are described herein with reference to cross section illustrations that are schematic illustrations of idealized embodiments of the present invention. As such, variations from the shapes of the illustrations as a result, for example, of manufacturing techniques and/or tolerances, are to be expected. Thus, embodiments of the present invention should not be construed as limited to the particular shapes of regions illustrated herein but are to include deviations in shapes that result, for example, from manufacturing. For example, a region illustrated or described as flat may, typically, have rough and/or nonlinear features. Moreover, sharp angles that are illustrated, typically, may be rounded. Thus, the regions illustrated in the figures are schematic in nature and their shapes are not intended to illustrate the precise shape of a region and are not intended to limit the scope of the present invention.

Unless otherwise defined, all terms (including technical and scientific terms) used herein have the same meaning as commonly understood by one of ordinary skill in the art to which this invention belongs. It will be further understood that terms, such as those defined in commonly used dictionaries, should be interpreted as having a meaning that is consistent with their meaning in the context of the relevant art and will not be interpreted in an idealized or overly formal sense unless expressly so defined herein.

Figures 1A-1H are side cross-sectional views of mounting substrates for semiconductor light emitting devices according to various embodiments of the present invention. Referring to Figure 1A, mounting substrates for semiconductor light emitting devices according to various embodiments of the invention include a solid metal block **100** having a cavity **110** in a first metal face **100a** thereof, that is configured to mount a semiconductor light emitting device therein, and to reflect light that is emitted by at least one semiconductor light emitting device that is mounted therein away from the cavity **110**. In some embodiments, the solid metal block **100** is a solid aluminum block or a solid steel block. The cavity **110** may be formed by machining, coining, etching and/or other conventional techniques. The size and shape of the cavity **110** may be configured to enhance or optimize the amount and/or direction of light that is reflected away from the cavity **110** from a semiconductor light emitting device that is mounted in the cavity **110**. For example, oblique

sidewalls **110a** and or a semi-ellipsoidal cross-sectional profile may be provided, so as to reflect light that is emitted by at least one semiconductor light emitting device that is mounted therein away from the cavity **110**. An additional reflective layer also may be provided on the cavity sidewall and/or floor, as will be described below.

5 Still referring to Figure 1A, the second metal face **100b** of the solid metal block **100** includes a plurality of heat sink fins **190** therein. The number, spacing and/or geometry of the heat sink fins **190** may be varied for desired heat dissipation, as is well known to those having skill in the art. Moreover, the heat sink fins need not be uniformly spaced, need not be straight, need not be rectangular in cross-section,
10 and can be provided in a one-dimensional elongated array and/or in a two-dimensional array of heat sink fin posts using techniques that are well known to those having skill in the art. Each fin may itself include one or more projecting fins thereon. In some embodiments, the metal block **100** may be a rectangular solid metal block of aluminum or steel about 6mm x about 9mm, and about 2mm thick, and the
15 cavity **110** may be about 1.2mm deep with a circular floor that is about 2.5mm in diameter, with sidewalls **110a** that are of any simple or complex shape to obtain desired radiation patterns. However, the block **100** may have other polygonal and/or ellipsoidal shapes. Moreover, in some embodiments, an array of 12 heat sink fins **190** may be provided, wherein the heat sink fins have a width of 2 mm, a pitch of 5 mm
20 and a depth of 9 mm. However, many other configurations of heat sink fins **190** may be provided. For example, many heat sink design profiles may be found on the Web at aavid.com.

 Figure 1B illustrates mounting substrates according to other embodiments of the present invention. As shown in Figure 1B, an electrically insulating coating **120** is
25 provided on the surface of the solid metal block **100**. The insulating coating **120** may be provided on the entire exposed surface of the solid metal block, including the heat sink fins **190**, or excluding the heat sink fins **190** as shown in Figure 1B, or on only a smaller portion of the exposed surface of the solid metal block. In some
 embodiments, as will be described below, the insulating coating **120** includes a thin
30 layer of aluminum oxide (Al_2O_3) that may be formed, for example, by anodic oxidation of the solid metal block **100** in embodiments where the solid metal block **100** is aluminum. In other embodiments, the insulating coating **120** includes a ceramic coating on a solid steel block **100**. In some embodiments, the coating **120** is

sufficiently thick to provide an electrical insulator, but is maintained sufficiently thin so as not to unduly increase the thermal conductive path therethrough.

Solid metal blocks **100** of aluminum including thin insulating coatings **120** of aluminum oxide may be provided using substrates that are marketed by the IRC
5 Advanced Film Division of TT Electronics, Corpus Christi, Texas, under the designation Anotherm™, that are described, for example, in brochures entitled *Thick Film Application Specific Capabilities* and *Insulated Aluminum Substrates*, 2002, both of which are available on the Web at irtctt.com. Moreover, solid metal blocks **100** of steel with an insulating coating **120** of ceramic may be provided using substrates that
10 are marketed by Heatron Inc., Leavenworth, Kansas, under the designation ELPOR®, that are described, for example, in a brochure entitled *Metal Core PCBs for LED Light Engines*, available on the Web at heatron.com. Cavities **110** and heat sink fins **190** may be provided in these solid metal blocks according to any of the embodiments described herein. Other solid metal blocks **100** with insulating coatings **120** may be
15 provided with at least one cavity **110** in a first metal face **100a** thereof, and a plurality of heat sink fins **190** in a second metal face **100b** thereof in other embodiments of the present invention.

Referring now to Figure 1C, first and second spaced apart conductive traces
· **130a**, **130b** are provided on the insulating coating **120** in the cavity **110**. The first and
20 second spaced apart conductive traces **130a**, **130b** are configured to connect to a semiconductor light emitting device that is mounted in the cavity **110**. As shown in Figure 1C, in some embodiments, the first and second spaced apart conductive traces **130a** and **130b** can extend from the cavity **110** onto the first face **100a** of the solid metal block **100**. When the insulating coating **120** is provided on only a portion of the
25 solid metal block **100**, it may be provided between the first and second spaced apart traces **130a** and **130b** and the solid metal block **100**, to thereby insulate the first and second metal traces **130a** and **130b** from the solid metal block **100**.

Figure 1D illustrates other embodiments of the present invention wherein the first and second spaced apart conductive traces **130a'**, **130b'** extend from the cavity
30 **110** to the first face **100a** around at least one side **100c** of the metal block and onto a second face **100b** of the metal block that is opposite the first face **100a**. Thus, backside contacts may be provided.

In some embodiments of the invention, the first and second spaced apart conductive traces **130a**, **130b** and/or **130a'**, **130b'** comprise metal and, in some

embodiments, a reflective metal such as silver. Thus, in some embodiments of the present invention, a conductive layer is provided on the insulating layer **120** that is patterned to provide a reflective coating in the cavity **110** and first and second conductive traces **130a**, **130b** that are configured to connect to at least one
5 semiconductor light emitting device that is mounted in the cavity **110**.

In other embodiments, as shown in Figure 1E, one or more separate reflective layers **132a**, **132b** may be provided on the spaced apart conductive traces **130a'**, **130b'** and/or in the cavity **110**. In these embodiments, the conductive traces **130a'**, **130b'** may comprise copper, and the reflective layers **132a**, **132b** may comprise
10 silver. In contrast, in embodiments of Figures 1C and/or 1D, the conductive traces may comprise silver to provide an integral reflector.

In still other embodiments, a separate reflector layer need not be provided. Rather, the surface of the cavity **110** including the sidewall **110a** may provide sufficient reflectance. Thus, the cavity **110** is configured geometrically to reflect light
15 that is emitted by at least one semiconductor light emitting device that is mounted therein, for example, by providing oblique sidewall(s) **110a**, reflective oblique sidewall(s) **110a** and/or a reflective coating **132a** and/or **132b** on the oblique sidewall(s) **110a** and/or on the floor of the cavity **110**, such that the dimensions and/or
sidewall geometry of the cavity act to reflect light that is emitted by at least one
20 semiconductor light emitting device that is mounted in the cavity **110**, away from the cavity **110**. Reflection may be provided or enhanced by the addition of a reflective coating **132a** and/or **132b** in the cavity **110**.

In still other embodiments of the present invention, as illustrated in Figure 1F, backside contacts may be provided by providing first and/or second through holes
25 **140a** and/or **140b**, which may be formed in the solid metal block **100** by machining, etching and/or other conventional techniques. Moreover, as shown in Figure 1F, the insulating coating **120** extends into the through holes **140a** and **140b**. First and second conductive vias **142a**, **142b** are provided in the first and second through holes **140a**, **140b**, and are insulated from the solid metal block **100** by the insulating coating
30 **120** in through holes **140a**, **140b**.

In Figure 1F, the through holes **140a** and **140b**, and the conductive vias **142a** and **142b** extend from the cavity **110** to the second face **100b**. The through holes **140a**, **140b** may be orthogonal and/or oblique to the first and second faces **100a**, **100b**. First and second spaced apart conductive traces **130a'**, **130b'** may be provided

in the cavity **110**, and electrically connected to the respective first and second conductive vias **142a**, **142b**. On the second face **100b**, third and fourth spaced apart conductive traces **130c**, **130d** also may be provided that are electrically connected to the respective first and second conductive vias **142a**, **142b**. A solder mask layer may be provided in some embodiments to isolate the third and fourth conductive traces **130c**, **130d** on the second face **100b**, to facilitate circuit board assembly. Solder mask layers are well known to those having skill in the art and need not be described further herein. As shown in Figure 1F, heat sink fins **190** may be provided in the center and/or at the edges of the solid metal block **100**, i.e., adjacent the cavity **110** and/or offset from the cavity **110**.

In embodiments of Figure 1F, the first and second through holes **140a**, **140b** and the first and second conductive vias **142a**, **142b** extended from the cavity **110** to the second face **100b**. In embodiments of Figure 1G, the first and second through holes **140a'**, **140b'** and the first and second conductive vias **142a'**, **142b'** extend from the first face **100a** outside the cavity **110** to the second face **100b**. The through holes **140a'**, **140b'** may be orthogonal and/or oblique to the first and second faces **100a**, **100b**. First and second spaced apart conductive traces **130a''**, **130b''** extend from the cavity **110** to the respective first and second conductive vias **142a'**, **142b'** on the first face **100a**. Third and fourth traces **130c'**, **130d'** are provided on the second face **100b** that electrically connect to the respective first and second conductive via **142a'**, **142b'**. As shown in Figure 1G, heat sink fins **190** may be provided in the center and/or at the edges of the solid metal block **100**, i.e., adjacent the cavity **110** and/or offset from the cavity **110**.

Figure 1H illustrates embodiments of the invention that were described in connection with Figure 1D, and which further include a semiconductor light emitting device **150** that is mounted in the cavity and that is connected to the first and second spaced apart electrical traces **130a'**, **130b'**. Moreover, Figure 1H illustrates that in other embodiments, a lens **170** extends across the cavity. In still other embodiments, an encapsulant **160** is provided between the semiconductor light emitting device **150** and the lens **170**. The encapsulant **160** may comprise clear epoxy and can enhance optical coupling from the semiconductor light emitting device **150** to the lens **170**. The encapsulant **160** also may be referred to herein as an optical coupling media. In some embodiments, a lens retainer **180** is provided on the solid metal block **100**, to

hold the lens **170** across the cavity **110**. In other embodiments, the lens retainer **180** may not be used.

The semiconductor light emitting device **150** can comprise a light emitting diode, laser diode and/or other device which may include one or more semiconductor layers, which may comprise silicon, silicon carbide, gallium nitride and/or other semiconductor materials, a substrate which may comprise sapphire, silicon, silicon carbide, gallium nitride or other microelectronic substrates, and one or more contact layers which may comprise metal and/or other conductive layers. The design and fabrication of semiconductor light emitting devices are well known to those having skill in the art.

For example, the light emitting device **150** may be gallium nitride based LEDs or lasers fabricated on a silicon carbide substrate such as those devices manufactured and sold by Cree, Inc. of Durham, North Carolina. For example, the present invention may be suitable for use with LEDs and/or lasers as described in United States Patent Nos. 6,201,262, 6,187,606, 6,120,600, 5,912,477, 5,739,554, 5,631,190, 5,604,135, 5,523,589, 5,416,342, 5,393,993, 5,338,944, 5,210,051, 5,027,168, 5,027,168, 4,966,862 and/or 4,918,497, the disclosures of which are incorporated herein by reference as if set forth fully herein. Other suitable LEDs and/or lasers are described in published U.S. Patent Publication No. US 2003/0006418 A1 entitled *Group III Nitride Based Light Emitting Diode Structures With a Quantum Well and Superlattice, Group III Nitride Based Quantum Well Structures and Group III Nitride Based Superlattice Structures*, published January 9, 2003, as well as published U.S. Patent Publication No. US 2002/0123164 A1 entitled *Light Emitting Diodes Including Modifications for Light Extraction and Manufacturing Methods Therefor*. Furthermore, phosphor coated LEDs, such as those described in United States Patent Application No. US 2004/0056260 A1, published on March 25, 2004, entitled *Phosphor-Coated Light Emitting Diodes Including Tapered Sidewalls, and Fabrication Methods Therefor*, the disclosure of which is incorporated by reference herein as if set forth fully, may also be suitable for use in embodiments of the present invention.

The LEDs and/or lasers may be configured to operate such that light emission occurs through the substrate. In such embodiments, the substrate may be patterned so as to enhance light output of the devices as is described, for example, in the above-cited U.S. Patent Publication No. US 2002/0123164 A1.

It will be understood by those having skill in the art that, although the embodiments of Figures 1A-1H have been illustrated as separate embodiments, various elements of Figures 1A-1H may be used together to provide various combinations and/or subcombinations of elements. Thus, for example, the reflective layer **132a**, **132b** may be used in any of the embodiments shown, and the semiconductor light emitting device **150**, lens **170**, encapsulant **160** and/or the lens retainer **180** may be used in any of the embodiments shown. Accordingly, the present invention should not be limited to the separate embodiments that are shown in Figures 1A-1H.

Figure 2 is a flowchart of steps that may be performed to package semiconductor light emitting devices according to various embodiments of the present invention. Referring to Figure 2, as shown at Block **210**, a solid block, such as an aluminum or steel block **100** of Figures 1A-1H, is provided including a cavity, such as cavity **110**, in a face thereof, that is configured to mount a semiconductor light emitting device therein and to reflect light that is emitted by at least one semiconductor light emitting device that is mounted therein away from the cavity **110**. The block **100** also includes therein a plurality of heat sink fins **190** on the second face **100b** thereof. As was described above, the cavity may be provided by machining, coining, etching and/or other conventional techniques. The heat sink fins **190** may also be provided by these and/or other techniques. Moreover, in other embodiments, the solid metal block may also contain the first and second spaced apart through holes such as through holes **140a**, **140b** and/or **140a'**, **140b'** that extend therethrough, and which may be fabricated by machining, etching and/or other conventional techniques.

Referring again to Figure 2, at Block **220**, an insulating coating is formed on at least some of the surface of the solid metal block. In some embodiments, a solid aluminum block is oxidized. In other embodiments, a ceramic coating is provided on a solid steel block. Other insulating coatings and other solid metal blocks may be provided. In some embodiments, the entire exposed surface of the solid metal block is coated. Moreover, when through holes are provided, the inner surfaces of the through holes also may be coated. In other embodiments, only portions of the metal block are coated, for example, by providing a masking layer on those portions which are desired not to be coated. Oxidization of aluminum is well known to those having skill in the art and may be performed, for example, using an anodic oxidation

processes and/or other oxidation processes, to provide a thin layer of Al_2O_3 on the aluminum. Ceramic coatings on steel are also well known to those having skill in the art and need not be described further herein.

Still referring to Figure 2, at Block **230**, first and second spaced apart
5 conductive traces, such as traces **130a**, **130b** and/or **130a'**, **130b'**, are fabricated in the cavity on the first face, on the sides and/or on the second face, depending on the configuration, as was described above. Moreover, in some embodiments, conductive vias, such as vias **142a**, **142b** and/or **142a'**, **142b'** may be fabricated in through holes. The conductive vias and/or the reflector layer may be fabricated prior to, concurrent
10 with and/or after the conductive traces. The fabrication of conductive traces on a solid metal block that is coated with an insulating layer is well known to provide circuit board-like structures with an aluminum, steel and/or other core, and accordingly need not be described in detail herein.

Finally, at Block **240**, other operations are performed to mount the
15 semiconductor device, lens, flexible film encapsulant and/or retainer on the substrate, as described herein. It also will be noted that in some alternate implementations, the functions/acts noted in the blocks of Figure 2 may occur out of the order noted in the flowchart. For example, two blocks shown in succession may, in fact, be executed substantially concurrently, or the blocks may sometimes be executed in the reverse
20 order, depending upon the functionality/acts involved.

Figures 3A and 3B are top and bottom perspective views, respectively, of packages according to embodiments of the present invention, which may correspond to the cross-sectional view of Figure 1D. Figures 3A and 3B illustrate the solid metal block **100**, the cavity **110**, the fins **190**, the first and second spaced apart conductive
25 traces **130a'**, **130b'** that wrap around the solid metal block, and the semiconductor light emitting device **150** mounted in the cavity **110**. The insulating coating **120** may be transparent and is not shown. A second insulating layer and/or solder mask may be provided on the first and/or second spaced apart conductive traces in these and/or any other embodiments.

30 Figure 4 illustrates an exploded perspective view of other embodiments of the present invention, which may correspond to Figure 1H. As shown in Figure 4, the solid metal block **100** includes a cavity **110** therein, and a plurality of spaced apart electrical traces thereon. In Figure 4, the first electrical trace **130a'** is shown. However, rather than a single second electrical trace, a plurality of second electrical

traces **330a'**, **330b'** and **330c'** may be provided to connect to a plurality of semiconductor light emitting devices **150'** that may be mounted in the cavity **110** to provide, for example, red, green and blue semiconductor light emitting devices for a white light source. The encapsulant **160** and lens retainer **180** are shown. Other configurations of lens retainers **180** can provide a ridge and/or other conventional mounting means for mounting a lens **170** on the solid metal block **100**. It also will be understood that an epoxy or other glue may be used in a lens retainer **180**. The lens retainer **180** may also provide additional top heat sinking capabilities in some embodiments of the present invention. Figure 5 illustrates the assembled package of Figure 4.

Accordingly, some embodiments of the present invention use a solid metal block as a mounting substrate for a semiconductor light emitting device and include one or more integral cavities and a plurality of integral heat sink fins. Aluminum or steel have sufficient thermal conductivity to be used as an effective heat sink when integral fins are provided. Additionally, the cost of the material and the cost of fabrication can be low. Moreover, the ability to grow high quality insulating oxides and/or provide ceramic coatings allows the desired electrical traces to be formed without a severe impact on the thermal resistance, since the thickness of the anodic oxidation or other coating can be precisely controlled. This insulating layer also can be selectively patterned, which can allow the addition of another plated metal to the substrate, such as plating silver on the cavity sidewalls only, for increased optical performance.

The ability to form an optical cavity and heat sink fins in the solid metal block, rather than a separate reflector cup and a separate heat sink, can reduce the assembly cost, since the total number of elements for the package can be reduced. Additionally, the fact that the reflector (cavity) position is fixed with respect to the solid metal block can also reduce the assembly complexity. Finally, the integral heat sink fins can enhance thermal efficiency. Embodiments of the invention may be particularly useful for high power semiconductor light emitting devices such as high power LEDs and/or laser diodes.

Other embodiments of solid metal block mounting substrates that may be used according to embodiments of the present invention are described in Application Serial No. 10/659,108, filed September 9, 2003, entitled *Solid Metal Block Mounting Substrates for Semiconductor Light Emitting Devices, and Oxidizing Methods For*

Fabricating Same, assigned to the assignee of the present invention, the disclosure of which is hereby incorporated herein by reference in its entirety as if set forth fully herein.

It is often desirable to incorporate a phosphor into the light emitting device, to enhance the emitted radiation in a particular frequency band and/or to convert at least some of the radiation to another frequency band. Phosphors may be included in a light emitting device using many conventional techniques. In one technique, phosphor is coated inside and/or outside a plastic shell of the device. In other techniques, phosphor is coated on the semiconductor light emitting device itself, for example using electrophoretic deposition. In still other embodiments, a drop of a material such as epoxy that contains phosphor therein may be placed inside the plastic shell, on the semiconductor light emitting device and/or between the device and the shell. LEDs that employ phosphor coatings are described, for example, in U.S. Patents, 6,252,254; 6,069,440; 5,858,278; 5,813,753; 5,277,840; and 5,959,316.

Some embodiments of the present invention that will now be described provide a coating including phosphor on the lens. In other embodiments, the lens includes phosphor dispersed therein.

Figures 6A-6H are cross-sectional views of transmissive optical elements according to various embodiments of the present invention. These optical elements may be used to package semiconductor light emitting devices as will also be described below.

As shown in Figure 6A, transmissive optical elements according to some embodiments of the present invention include a lens **170** that comprises transparent plastic. As used herein, the term "transparent" means that optical radiation from the semiconductor light emitting device can pass through the material without being totally absorbed or totally reflected. The lens **170** includes phosphor **610** dispersed therein. As is well known to those having skill in the art, the lens **170** may comprise polycarbonate material and/or other conventional plastic materials that are used to fabricate transmissive optical elements. Moreover, the phosphor **610** can comprise any conventional phosphor including cerium-doped YAG and/or other conventional phosphors. In some specific embodiments, the phosphor comprises Cerium doped Yttrium Aluminum Garnet (YAG:Ce). In other embodiments, nano-phosphors may be used. Phosphors are well known to those having skill in the art and need not be described further herein.

in Figure 6A, the phosphor **610** is uniformly dispersed within the lens **170**. In contrast, in Figure 6B, the phosphor **620** is nonuniformly dispersed in the lens **170**. Various patterns of phosphor **620** may be formed, for example, to provide areas of higher intensity and/or different color and/or to provide various indicia on the lens **170** when illuminated. In Figures 6A-6B, the lens **110** is a dome-shaped lens. As used herein, the terms "dome" and "dome-shaped" refer to structures having a generally arcuate surface profile, including regular hemispherical structures as well as other generally arcuate structures that do not form a regular hemisphere, which are eccentric in shape and/or have other features, structures and/or surfaces.

Referring now to Figure 6C, one or more coatings **630** may be provided on the outside of the lens **170**. The coating may be a protective coating, a polarizing coating, a coating with indicia and/or any other conventional coating for an optical element that is well known to those having skill in the art. In Figure 6D, one or more inner coatings **640** is provided on the inner surface of the lens **170**. Again, any conventional coating or combination of coatings may be used.

Moreover, other embodiments of the invention provide both an inner and an outer coating for the lens **170** that includes uniformly distributed phosphor **610** and/or nonuniformly distributed phosphor **620** therein. By providing an inner and outer coating, improved index matching to the phosphor may be provided. Thus, three layers may be injection molded according to some embodiments of the present invention. Other embodiments of the present invention can use an index matching media, such as a liquid and/or solid gel, within the shell, to assist in index matching. The use of inner and outer layers can reduce the number of photons that can be trapped in the phosphor-containing layer due to index matching issues.

Figure 6E describes other embodiments of the present invention wherein a transparent inner core **650** is provided inside the lens **170**. In some embodiments, as also shown in Figure 6E, the transparent inner core **650** fills the lens **170**, to provide a hemispherical optical element. The transparent inner core **650** may be uniformly transparent and/or may include translucent and/or opaque regions therein. The transparent inner core **650** may comprise glass, plastic and/or other optical coupling media.

Figure 6F illustrates other embodiments of the present invention wherein a phosphor-containing lens **170** is combined with a semiconductor light emitting device

150 that is configured to emit light **662** into and through the transparent inner core **650** and through the lens **170**, to emerge from the lens **170**.

Figure 6G is a cross-sectional view of other embodiments of the present invention. As shown in Figure 6G, a mounting substrate **100** is provided, such that
5 the light emitting device **150** is between the mounting substrate **100** and the transparent inner core **650**. As also shown in Figure 6G, the mounting substrate **100** includes a cavity **110** therein and the light emitting device **150** is at least partially in the cavity **110**. Heat sink fins **190** also are provided.

Figure 6H illustrates yet other embodiments of the present invention. In these
10 embodiments, the cavity **110** may be filled with an encapsulant **680**, such as epoxy and/or other optical coupling media (e.g., silicon). The encapsulant **680** can enhance optical coupling from the light emitting device **150** to the transparent inner core **650**. Heat sink fins **190** also are provided.

It will be understood by those having skill in the art that, although the
15 embodiments of Figures 6A-6H have been illustrated as separate embodiments, various elements of Figures 6A-6H may be used together in various combinations and subcombinations of elements. Thus, for example, combinations of inner and outer coatings **640** and **630**, uniformly distributed phosphor **610** and nonuniformly distributed phosphor **620**, light emitting devices **150**, mounting substrates **100**,
20 cavities **110**, inner cores **650** and encapsulant **680** may be used together. Moreover, embodiments of Figures 6A-6H may be combined with any other embodiments disclosed herein.

Figure 7 is a cross-sectional view of light emitting devices according to other embodiments of the present invention. As shown in Figure 7, these embodiments
25 include a lens **170** which may be made of optically transparent material that is loaded with phosphor and/or other chemicals. An inner core **650** may be made of optically transparent material such as plastic or glass and may be placed on an encapsulating-containing cavity **110** in a mounting substrate **100** including heat sink fins **190**. The lens **170** and the inner core **650** form a composite lens for a light emitting diode **150**.

30 Figure 8 is a schematic block diagram of an apparatus for forming transmissive optical elements according to various embodiments of the present invention. In particular, Figure 8 illustrates an injection molding apparatus that may be used to form transmissive optical elements according to various embodiments of the present invention. As shown in Figure 8, an injection molding apparatus includes

a hopper **810** or other storage device in which a transparent plastic and/or phosphor additive **850** are provided. The transparent plastic and/or phosphor additive may be provided in pellet, powder and/or solid form. Other additives, such as solvents, binders, etc. may be included, as is well known to those having skill in the art. An injector **820** may include a heater and a screw mechanism that is used to melt the transparent plastic and phosphor additive and/or maintain these materials in a melted state, to provide a molten liquid that comprises transparent plastic and the phosphor additive. The injector **820** injects the molten liquid into a mold **840** via nozzle **830**. The mold **840** includes an appropriate channel **860** therein, which can be used to define the shape of the optical element, such as a dome or keypad key. Injection molding of optical elements is well known to those having skill in the art and is described, for example, in U.S. Patents 4,826,424; 5,110,278; 5,882,553; 5,968,422; 6,156,242 and 6,383,417, and need not be described in further detail herein. It also will be understood that casting techniques also may be used, wherein molten liquid that comprises a transparent plastic and a phosphor additive is provided in a female mold which is then coupled to a male mold (or vice versa) to cast the optical element. Casting of optical elements is described, for example, in U.S. Patents 4,107,238; 4,042,552; 4,141,941; 4,562,018; 5,143,660; 5,374,668; 5,753,730 and 6,391,231, and need not be described in further detail herein.

Figure 9 is a flowchart of steps that may be used to package semiconductor light emitting devices according to various embodiments of the present invention. As shown in Figure 9, at Block **910**, a mold, such as mold **840** of Figure 8, is filled with molten liquid that comprises a transparent plastic and a phosphor additive. At Block **920**, the molten liquid is allowed to solidify to produce the optical element having phosphor dispersed therein. The optical element is then removed from the mold and mounted across a cavity in a solid metal block.

Figure 10 is a flowchart of steps that may be performed to package semiconductor light emitting devices according to embodiments of the present invention. As shown in Figure 10 at Block **1010**, a lens, such as a dome-shaped lens **170**, that comprises a transparent plastic including a phosphor dispersed therein, is molded using injection molding, casting and/or other conventional techniques. At Block **1020**, a core such as a core **650** of Figure 6E is formed. It will be understood that, in some embodiments, the core **650** is placed or formed inside the lens **170**, whereas, in other embodiments, Block **1020** precedes Block **1010** by forming a

transparent core **650** and filling a mold that includes a transparent core **650** with a molten liquid that comprises a transparent plastic and a phosphor additive, to form the lens **170** around the transparent core.

Still referring to Figure 10, a semiconductor light emitting device, such as device **150**, is placed in a reflective cavity **110** of a mounting substrate such as mounting substrate **100**. At Block **1040**, an encapsulant, such as encapsulant **680** of Figure 6H, is applied to the mounting substrate **100**, the light emitting device **150** and/or the core **650**. Finally, at Block **1050**, the lens or shell is mated to the mounting substrate using an epoxy, a snap-fit and/or other conventional mounting techniques.

It may be desirable for the inner core **650** to fill the entire lens, so as to reduce or minimize the amount of encapsulant **680** that may be used. As is well known to those having skill in the art, the encapsulant **680** may have a different thermal expansion coefficient than the mounting substrate **100** and/or the inner core **650**. By reducing or minimizing the amount of encapsulant **680** that is used at Block **1040**, the effect of these thermal mismatches can be reduced or minimized.

It should also be noted that in some alternate implementations, the functions/acts noted in the blocks of Figures 9 and/or 10 may occur out of the order noted in the flowcharts. For example, two blocks shown in succession may in fact be executed substantially concurrently or the blocks may sometimes be executed in the reverse order, depending upon the functionality/acts involved.

Accordingly, some embodiments of the present invention can form a composite optical element such as a lens using molding or casting techniques. In some embodiments, injection molding can be used to place a phosphor layer dispersed in the molding material on the inner or outer surface and then completing the molding or casting process in the remaining volume, to form a desired optical element. These optical elements can, in some embodiments, convert a blue light emitting diode behind the lens, to create the appearance of white light.

Other embodiments of the present invention may use the phosphor to evenly disperse the light and/or to disperse the light in a desired pattern. For example, conventional light emitting devices may emit light in a "Batwing" radiation pattern, in which greater optical intensity is provided at off-axis angles, such as angles of about 40° off-axis, compared to on-axis (0°) or at the sides (for example, angles greater than about 40°). Other light emitting diodes may provide a "Lambertian" radiation pattern, in which the greatest intensity is concentrated in a central area to about 40° off-axis

and then rapidly drops off at larger angles. Still other conventional devices may provide a side emitting radiation pattern, wherein the greatest light intensity is provided at large angles, such as 90° from the axis, and falls rapidly at smaller angles approaching the axis. In contrast, some embodiments of the present invention can
5 reduce or eliminate angular-dependent radiation patterns of light output from a light emitting device, such as angular dependence of Color Correlated Temperature (CCT). Thus, light intensity and the x,y chromaticity values/coordinates from all surfaces of the lens can remain relatively constant in some embodiments. This may be advantageous when used for illumination applications, such as a room where a
10 spotlight effect is not desirable.

Injection molding processes as described above, according to some embodiments of the invention, can allow formation of a single optical element with multiple features, such as lensing and white conversion. Additionally, by using a two-molding or casting technique, according to some embodiments, one can shape the
15 phosphor layer to its desired configuration, to reduce or minimize the angular dependence of color temperature with viewing angle.

Other embodiments of lenses including phosphor dispersed therein are described in Application Serial No. 10/659,240, filed September 9, 2003, entitled
20 *Transmissive Optical Elements Including Transparent Plastic Shell Having a Phosphor Dispersed Therein, and Methods of Fabricating Same*, assigned to the assignee of the present invention, the disclosure of which is hereby incorporated by reference in its entirety as if set forth fully herein.

In other embodiments of the present invention, a coating including phosphor is provided on the semiconductor light emitting device **150** itself. In particular, it may
25 be desirable to provide a phosphor for an LED, for example to provide solid-state lighting. In one example, LEDs that are used for solid-state white lighting may produce high radiant flux output at short wavelengths, for example in the range of about 380nm to about 480nm. One or more phosphors may be provided, wherein the short wavelength, high energy photon output of the LED is used to excite the
30 phosphor, in part or entirely, to thereby down-convert in frequency some or all of the LED's output to create the appearance of white light.

As one specific example, ultraviolet output from an LED at about 390nm may be used in conjunction with red, green and blue phosphors, to create the appearance of white light. As another specific example, blue light output at about 470nm from an

LED may be used to excite a yellow phosphor, to create the appearance of white light by transmitting some of the 470nm blue output along with some secondary yellow emission occurring when part of the LEDs output is absorbed by the phosphor.

Phosphors may be included in a semiconductor light emitting device using many conventional techniques. In one technique, phosphor is coated inside and/or outside the plastic shell of an LED. In other techniques, phosphor is coated on the semiconductor light emitting device itself, for example using electrophoretic deposition. In still other techniques, a drop of a material, such as epoxy that contains phosphor therein, may be placed inside the plastic shell, on the semiconductor light emitting device and/or between the device and the shell. This technique may be referred to as a "glob top". The phosphor coatings may also incorporate an index matching material and/or a separate index matching material may be provided.

Moreover, as was described above, published United States Patent Application No. US 2004/0056260 A1 describes a light emitting diode that includes a substrate having first and second opposing faces and a sidewall between the first and second opposing faces that extends at an oblique angle from the second face towards the first face. A conformal phosphor layer is provided on the oblique sidewall. The oblique sidewall can allow more uniform phosphor coatings than conventional orthogonal sidewalls.

Semiconductor light emitting devices are fabricated, according to other embodiments of the present invention, by placing a suspension comprising phosphor particles suspended in solvent on at least a portion of a light emitting surface of a semiconductor light emitting device, and evaporating at least some of the solvent to cause the phosphor particles to deposit on at least a portion of the light emitting surface. A coating comprising phosphor particles is thereby formed on at least a portion of the light emitting surface.

As used herein, a "suspension" means a two-phase solid-liquid system in which solid particles are mixed with, but undissolved ("suspended"), in liquid ("solvent"). Also, as used herein, a "solution" means a single-phase liquid system in which solid particles are dissolved in liquid ("solvent").

Figure 11A is a cross-sectional view of a semiconductor light emitting device package during an intermediate fabrication step according to various embodiments of the present invention. As shown in Figure 11A, a suspension **1120** including phosphor particles **1122** suspended in solvent **1124** is placed on at least a portion of a

light emitting surface **150a** of a semiconductor light emitting device **150**. As used herein, "light" refers to any radiation, visible and/or invisible (such as ultraviolet) that is emitted by a semiconductor light emitting element **150**. At least some of the solvent **1124** is then evaporated, as shown by the arrow linking Figures 11A and 11B, to cause the phosphor particles **1122** to deposit on at least the portion of the light emitting surface **150a**, and form a coating **1130** thereon including the phosphor particles **1122**. In some embodiments, the suspension **1120** including phosphor particles **1122** suspended in solvent **1124** is agitated while performing the placing of Figure 11A and/or while performing the evaporating. Moreover, as shown in Figure 11B, evaporating can be performed to cause the phosphor particles **122** to uniformly deposit on at least the portion of the light emitting surface **150a**, to thereby form a uniform coating **1130** of the phosphor particles **1122**. In some embodiments, the phosphor particles **1122** uniformly deposit on all the light emitting surface **150a**. Moreover, in some embodiments, substantially all of the solvent **1124** can be evaporated. For example, in some embodiments, at least about 80% of the solvent can be evaporated. In some embodiments, substantially all the solvent **1124** is evaporated to cause the phosphor particles **1122** to uniformly deposit on all the light emitting surface **150a**.

In some embodiments of the present invention, the solvent **1124** comprises Methyl Ethyl Ketone (MEK), alcohol, toluene, Amyl Acetate and/or other conventional solvents. Moreover, in other embodiments, the phosphor particles **1122** may be about 3-4 μ m in size, and about 0.2gm of these phosphor particles **1122** may be mixed into about 5cc of MEK solvent **1124**, to provide the suspension **1120**. The suspension **1120** may be dispensed via an eyedropper pipette, and evaporation may take place at room temperature or at temperatures above or below room temperature, such as at about 60°C and/or at about 100°C.

Phosphors also are well known to those having skill in the art. As used herein, the phosphor particles **1122** may be Cerium-doped Yttrium Aluminum Garnet (YAG:Ce) and/or other conventional phosphors and may be mixed into the solvent **1124** using conventional mixing techniques, to thereby provide the suspension **1120** comprising phosphor particles **1122**. In some embodiments, the phosphor is configured to convert at least some light that is emitted from the light emitting surface **150a** such that light that emerges from the semiconductor light emitting device appears as white light.

Figure 12A is a cross-sectional view of other embodiments of the present invention. As shown in Figure 12A, a mounting substrate **100** is provided, and the semiconductor light emitting element **150** is mounted in a cavity **110** therein. Heat sink fins **190** also are provided. The suspension **1120** including phosphor particles **1122** suspended in solvent **1124** is placed in the cavity **110**. Thus, the cavity **110** can be used to confine the suspension **1120** and thereby provide a controlled amount and geometry for the suspension **1120**.

Referring now to Figure 12B, evaporation is performed, to thereby evaporate at least some of the solvent **1124** to cause the phosphor particles **1122** to deposit on at least a portion of the light emitting surface **150a**, and form a coating **1130** including the phosphor particles **1122**.

Figures 13A and 13B illustrate other embodiments of the present invention. As shown in Figure 13A, in these embodiments, the cavity **110** includes a cavity floor **110b**, and the semiconductor light emitting device **150** is mounted on the cavity floor **110b**. Moreover, the semiconductor light emitting device **150** protrudes away from the cavity floor **110b**. In some embodiments, the light emitting surface **150a** of the semiconductor light emitting device **150** includes a face **150b** that is remote from the cavity floor **110b**, and a sidewall **150c** that extends between the face **150b** and the cavity floor **110b**. As shown in Figure 13B, evaporation is performed to evaporate at least some of the solvent **1124**, to cause the phosphor particles **1122** to uniformly deposit on at least a portion of the light emitting surface **150a** and thereby form a coating **1130** of uniform thickness comprising the phosphor particles **1122**. As also shown in Figure 13B, in some embodiments, the coating may be of uniform thickness on the face **150b** and on the sidewall **150c**. In some embodiments, the coating **1130** may extend uniformly on the floor **110b** outside the light emitting element **150**. In other embodiments, the coating **1130** also may extend at least partially onto sidewalls **110a** of the cavity **110**.

In other embodiments of the present invention, a binder may be added to the suspension **1120** so that, upon evaporation, the phosphor particles **1122** and the binder deposit on at least the portion of the light emitting surface **150a**, and form a coating thereon comprising the phosphor particles **1122** and the binder. In some embodiments, a cellulose material, such as ethyl cellulose and/or nitro cellulose, may be used as a binder. Moreover, in other embodiments, at least some of the binder may evaporate along with the solvent.

In other embodiments of the present invention, the suspension **1120** includes the phosphor particles **1122** and light scattering particles suspended in solvent **1124**, and wherein at least some of the solvent **1124** is evaporated to cause the phosphor particles **1122** and the light scattering particles to deposit on at least a portion of the light emitting device **150**, and form a coating **1130** including the phosphor particles **1122** and the light scattering particles. In some embodiments, the light scattering particles may include SiO₂ (glass) particles. By selecting the size of the scattering particles, blue light may be effectively scattered to make the emission source (for white applications) more uniform (more specifically, random), in some embodiments.

It will also be understood that combinations and subcombinations of embodiments of Figures 11A-13B also may be provided, according to various embodiments of the invention. Moreover, combinations and subcombinations of embodiments of Figures 11A-13B with any or all of the other figures also may be provided according to various embodiments of the invention. Other embodiments of coating a semiconductor light emitting device by evaporating solvents from a suspension are described in Application Serial No. 10/946,587, filed September 21, 2004, entitled *Methods of Coating Semiconductor Light Emitting Elements by Evaporating Solvent From a Suspension*, assigned to the assignee of the present invention, the disclosure of which is hereby incorporated herein by reference in its entirety as if set forth fully herein. Other embodiments of coating a semiconductor light emitting device by coating a patternable film including transparent silicone and phosphor on a semiconductor light emitting device are described in Application Serial No. 10/947,704, filed September 23, 2004, entitled *Semiconductor Light Emitting Devices Including Patternable Films Comprising Transparent Silicone and Phosphor, and Methods of Manufacturing Same*, assigned to the assignee of the present invention, the disclosure of which is hereby incorporated herein by reference in its entirety as if set forth fully herein.

Other embodiments of the invention provide a flexible film that includes an optical element therein on the first metal face, wherein the optical element extends across the cavity. In some embodiments, the optical element is a lens. In other embodiments, the optical element may include a phosphor coating and/or may include phosphor dispersed therein.

Figure 14 is an exploded cross-sectional view of semiconductor light emitting device packages and assembling methods therefor, according to various embodiments

of the present invention. Referring to Figure 14, these semiconductor light emitting device packages include a solid metal block **100** having a first face **100a** including a cavity **110** therein, and a second face **100b**, including a plurality of heat sink fins **190** therein. A flexible film **1420**, including therein an optical element **1430**, is provided
5 on the first face **100a**, and a semiconductor light emitting device **150** is provided between the metal block **100** and the flexible film **1120**, and configured to emit light **662** through the optical element. An attachment element **1450** may be used to attach the flexible film **1420** and the solid metal block **100** to one another.

Still referring to Figure 14, the flexible film **1420** can provide a cover slip that
10 can be made of a flexible material such as a conventional Room Temperature Vulcanizing (RTV) silicone rubber. Other silicone-based and/or flexible materials may be used. By being made of a flexible material, the flexible film **1420** can conform to the solid metal block **100** as it expands and contracts during operations. Moreover, the flexible film **1420** can be made by simple low-cost techniques such as
15 transfer molding, injection molding and/or other conventional techniques that are well known to those having skill in the art.

As described above, the flexible film **1420** includes therein an optical element **1430**. The optical element can include a lens, a prism, an optical emission enhancing and/or converting element, such as a phosphor, an optical scattering element and/or
20 other optical element. One or more optical elements **1430** also may be provided, as will be described in detail below. Moreover, as shown in Figure 14, an optical coupling media **1470**, such as an optical coupling gel and/or other index matching material, may be provided between the optical element **1430** and the semiconductor light emitting device **150**, in some embodiments.

Still referring to Figure 14, the attachment element **1450** can be embodied as
25 an adhesive that may be placed around the periphery of the solid metal block **100**, around the periphery of the flexible film **1420** and/or at selected portions thereof, such as at the corners thereof. In other embodiments, the solid metal block **100** may be coined around the flexible film **1420**, to provide an attachment element **1450**. Other
30 conventional attaching techniques may be used.

Figure 14 also illustrates methods of assembling or packaging semiconductor light emitting devices according to various embodiments of the present invention. As shown in Figure 14, a semiconductor light emitting element **150** is mounted in a cavity **110** in a first face **100a** of a solid metal block **100** that includes fins **190** on a

second face **100b** thereof. A flexible film **1420** that includes therein an optical element **1430** is attached to the first face **100a**, for example using an attachment element **1450**, such that, in operation, the semiconductor light emitting device **150** emits light **662** through the optical element **1430**. In some embodiments, an optical coupling media **1470** is placed between the semiconductor light emitting device **150** and the optical element **1430**.

Figure 15 is a cross-sectional view of packaged semiconductor light emitting devices of Figure 14, according to other embodiments of the present invention. The flexible film **1420** extends onto the face **100a** beyond the cavity **110**. The optical element **1430** overlies the cavity **110**, and the semiconductor light emitting device **150** is in the cavity **110**, and is configured to emit light **662** through the optical element **1430**. In Figure 15, the optical element **1430** includes a concave lens. In some embodiments, an optical coupling media **1470** is provided in the cavity **110** between the optical element **1430** and the semiconductor light emitting device **150**. In some embodiments, the optical coupling media **1470** fills the cavity **110**.

Figure 16 is a cross-sectional view of other embodiments of the present invention. As shown in Figure 16, two optical elements **1430** and **1630** are included in the flexible film **1420**. A first optical element **1430** includes a lens and a second optical element **1630** includes a prism. Light from the semiconductor light emitting device **150** passes through the prism **1630** and through the lens **1430**. An optical coupling media **1470** also may be provided. In some embodiments, the optical coupling media **1470** fills the cavity **110**. The optical coupling media **1470** may have a sufficient difference in index of refraction from the prism **1630** such that the prism **1630** can reduce shadowing. As shown in Figure 16, the semiconductor light emitting device **150** includes a wire **1650** that extends towards the flexible film **1420**, and the prism **1630** is configured to reduce shadowing by the wire **1650** of the light that is emitted from the semiconductor light emitting device **150**. More uniform light emissions thereby may be provided, with reduced shadowing of the wire **1650**. It will be understood that the term "wire" is used herein in a generic sense to encompass any electrical connection for the semiconductor light emitting device **150**.

Figure 17 is a cross-sectional view of other embodiments of the present invention. As shown in Figure 17, phosphor **1710** is provided on the flexible film **1320** between the lens **1430** and the semiconductor light emitting device **150**. The phosphor **410** can include cerium-doped Yttrium Aluminum Garnet (YAG) and/or

other conventional phosphors. In some embodiments, the phosphor comprises Cerium doped Yttrium Aluminum Garnet (YAG:Ce). In other embodiments, nano-phosphors may be used. Phosphors are well known to those having skill in the art and need not be described further herein. An optical coupling media **1470** also may be
5 provided that may fill the cavity **110**.

Figure 18 illustrates yet other embodiments of the present invention. In these embodiments, the lens **1430** includes a concave inner surface **1430a** adjacent the semiconductor light emitting device **150**, and the phosphor **1710** includes a conformal phosphor layer on the concave inner surface **1430a**. An optical coupling media **1470**
10 also may be provided that may fill the cavity **110**.

Figure 19 is a cross-sectional view of other embodiments. As shown in Figure 19, at least a portion **1420d** of the flexible film **1420** that overlies the cavity **110** is transparent to the light. Moreover, at least a portion **1420c** of the flexible film **1420** that extends onto the face **100a** beyond the cavity **110** is opaque to the light, as shown
15 by the dotted portions **1420c** of the flexible film **1420**. The opaque regions **1420c** can reduce or prevent bouncing of light rays, and thereby potentially produce a more desirable light pattern. An optical coupling media **1470** also may be provided that may fill the cavity **110**.

Figure 20 is a cross-sectional view of other embodiments of the present invention wherein the flexible film **1420** may be fabricated of multiple materials. As shown in Figure 20, at least a portion **1420d** of the flexible film **1420** that overlies the cavity **110** includes a first material, and at least a portion **1420c** of the flexible film **1420** that extends onto the face **100a** beyond the cavity **110** includes a second material. Two or more materials may be used in the flexible film **1420** in some
25 embodiments, to provide different characteristics for the portion of the flexible film **1420** through which light is emitted and through which light is not emitted. Multiple materials may be used for other purposes in other embodiments. For example, an inflexible and/or flexible plastic lens may be attached to a flexible film. Such a flexible film **1420** with multiple materials may be fabricated using conventional
30 multiple molding techniques, for example. In some embodiments, the first material that is molded may not be fully cured, so as to provide a satisfactory bond that attaches to the second material that is subsequently molded. In other embodiments, the same material may be used for the optical element and the flexible film, wherein the optical element is formed and then the flexible film is formed surrounding the

optical element. An optical coupling media **1470** also may be provided that may fill the cavity **110**.

Figure 21 is a cross-sectional view of other embodiments of the present invention. In these embodiments, the semiconductor light emitting element **150** includes a wire **1650**, that extends towards and contacts the flexible film **1420** in the cavity **110**. The flexible film **1420** includes a transparent conductor **2110** which can include Indium Tin Oxide (ITO) and/or other conventional transparent conductors. The transparent conductor **2110** extends in the cavity **110** and electrically connects to the wire. Reduced shadowing by the wire **1650** thereby may be provided. Moreover, a wire bond to the metal block **100**, and the potential consequent light distortion, may be reduced or eliminated. An optical coupling media **1470** also may be provided that may fill the cavity **110**.

Figure 22 is a cross-sectional view of other embodiments of the present invention. As shown in Figure 22, the optical element **1430** includes a lens that overlies the cavity **110** and protrudes away from the cavity **110**. The flexible film **1420** further includes a protruding element **2230** between the lens **1430** and the light emitting element **150** that protrudes towards the cavity **110**. As shown in Figure 22, a conformal phosphor layer **1710** is provided on the protruding element **2230**. By providing the protruding element **2230** on the back of the lens **1430**, optical coupling media **1470** in the device may be displaced. Arrangements of Figure 22 may thus provide more uniform phosphor coating at desired distances from the light emitting element **150**, so as to provide more uniform illumination. The optical coupling media **1470** may fill the cavity **110**.

Figures 23 and 24 illustrate packages including multiple semiconductor light emitting devices and/or multiple optical elements according to various embodiments of the present invention. For example, as shown in Figure 23, the optical element **1430** is a first optical element, and the semiconductor light emitting device **150** is a first semiconductor light emitting device. The flexible film **1420** also includes therein a second optical element **1430'** that is spaced apart from the first optical element **1430**, and the device further includes a second semiconductor light emitting device **150'** between the substrate **100** and the flexible film **1420**, and configured to emit light through the second optical element **1430'**. Moreover, a third optical element **1430''** and a third semiconductor light emitting device **150''** also may be provided. The optical elements **1430**, **1430'** and **1430''** may be the same and/or different from

one another, and the semiconductor light emitting devices **150**, **150'** and **150''** may be the same and/or different from one another. Moreover, in embodiments of Figure 23, the cavity **110** is a first cavity, and second and third cavities **110'**, **110''**, respectively, are provided for the second and third semiconductor light emitting devices **150'**, **150''**, respectively. The cavities **110**, **110'** and **110''** may be the same and/or may have different configurations from one another. An optical coupling media **1470** also may be provided that may fill the cavity or cavities. It will be understood that larger or smaller numbers of semiconductor light emitting devices and/or cavities may be provided in other embodiments.

As also shown in Figure 23, the phosphor **1710** may be a first phosphor layer, and second and/or third phosphor layers **1710'** and **1710''**, respectively, may be provided on the flexible film **1420** between the second optical element **1430'** and the second semiconductor light emitting device **150'**, and between the third optical element **1430''** and the third semiconductor light emitting device **150''**, respectively. The phosphor layers **1710**, **1710'**, **1710''** may be the same, may be different and/or may be eliminated. In particular, in some embodiments of the present invention, the first phosphor layer **1710** and the first semiconductor light emitting device **150** are configured to generate red light, the second phosphor layer **1710'** and the second semiconductor light emitting device **150'** are configured to generate blue light, and the third phosphor layer **1710''** and the third semiconductor light emitting device **150''** are configured to generate green light. A Red, Green, Blue (RGB) light emitting element that can emit white light thereby may be provided in some embodiments.

Figure 24 is a cross-sectional view of other embodiments of the present invention. In these embodiments, a single cavity **2400** is provided for the first, second and third semiconductor light emitting devices **150**, **150'** and **150''**, respectively. An optical coupling media **1470** also may be provided that may fill the cavity **2400**. It will be understood that larger or smaller numbers of semiconductor light emitting devices and/or cavities may be provided in other embodiments.

Figure 25 is a cross-sectional view of yet other embodiments of the present invention. In Figure 25, the optical element **2530** comprises a lens having phosphor dispersed therein. Many embodiments of lenses including phosphor dispersed therein were described above and need not be repeated. In still other embodiments of the present invention, an optical scattering element may be embedded in the lens as

shown in Figure 25, and/or provided as a separating layer as shown, for example, in Figure 22, in addition or instead of phosphor.

Figure 26 is a perspective view of a semiconductor light emitting device package according to other embodiments of the present invention.

5 It will be understood by those having skill in the art that various embodiments of the invention have been described individually in connection with Figures 14-26. However, combinations and subcombinations of the embodiments of Figures 14-26 may be provided according to various embodiments of the present invention, and also may be combined with embodiments according to any of the other figures described
10 herein.

Figure 27 is a cross-sectional view of a semiconductor light emitting device package according to various embodiments of the present invention. As shown in Figure 27, a solid metal block **100** includes a plurality of cavities **110** in a first metal face **100a** thereof, and a plurality of heat sink fins **190** in a second metal face **100b**
15 thereof. An insulating layer **120** is provided on the first metal face **100a**. A conductive layer **130** is provided on the insulating layer, and is patterned to provide a reflective coating **2730a** in the cavity **110**, and first **2730b** and second **2730c** conductive traces in the cavity **110** that are configured to connect to at least one semiconductor light emitting device **150** that is mounted in the cavity. As shown in
20 Figure 27, the traces can provide series connection between the semiconductor light emitting devices. However, parallel and/or series/parallel or anti-parallel connections also may be provided. It will be understood that larger or smaller numbers of semiconductor light emitting devices and/or cavities may be provided in other embodiments.

25 Still referring to Figure 27, a flexible film **1420** that includes an optical element **1430** such as a lens therein, is provided on the first metal face **100a**, wherein a respective optical element **1430** extends across a respective cavity **110**. Various embodiments of flexible films **1420** and optical elements **1430** may be provided as was described extensively above. Moreover, phosphor may be integrated as was
30 described extensively above. In other embodiments, discrete lenses **170** also may be provided, instead of the flexible film **1420** containing optical elements **1430**. In some embodiments, the conductor **130** is connected to an integrated circuit **2710**, such as the light emitting device driver integrated circuit, on the solid metal block **110**. In

some embodiments, a semiconductor light emitting package of Figure 27 can be configured to provide a plug-in substitute for a conventional light bulb.

Figure 28 is a perspective view of embodiments according to Figure 27. As shown in Figure 28, an array of cavities **110** that are connected by a conductive layer **130** may be provided on the first face **100a** of a solid metal block **100**. In Figure 28, a uniformly spaced 10%10 array of cavities and a corresponding 10%10 array of optical elements **1430** on a flexible film **1420**, is shown. However, larger or smaller arrays may be provided and the arrays may be circular, randomly spaced and/or of other configuration. Moreover, nonuniform spacing may be provided in some or all portions of the array of cavities **110** and optical elements **1430**. More specifically, uniform spacing may promote uniform light output, whereas nonuniform spacing may be provided to compensate for variations in heat dissipation abilities of the heat sink fins **190** across various portions of the solid metal block **100**.

It will also be understood that embodiments of Figures 27 and 28 may be combined in various combinations and subcombinations with any of the other embodiments described herein.

Figure 29 is a side cross-sectional view of other embodiments of the present invention. In these embodiments, the first metal face **100a** further includes a plurality of pedestals **2900** therein, and a respective one of the plurality of cavities **110** is in a respective one of the plurality of pedestals **2900**. The insulating layer **120** and conductive layer **130** are not illustrated in Figure 29 for the sake of clarity. Multiple cavities **110** also may be provided in a given pedestal **2900** in other embodiments. In embodiments of Figure 29, the flexible film **1420'** includes a plurality of optical elements **1430'**, such as lenses, a respective one of which extends across a respective pedestal **2900** and across a respective cavity **110**. It will be understood that larger or smaller numbers of semiconductor light emitting devices and/or cavities may be provided in other embodiments.

By providing pedestals **2900** according to some embodiments of the present invention, the light emitting devices **150** may be placed closer to the radial center of the optical elements **1430'**, to thereby allow the uniformity of emissions to be enhanced. It will also be understood that embodiments of Figure 29 may be provided with discrete optical elements, such as lenses, a respective one of which spans across a respective pedestal **2900** and cavity **110**, and that embodiments of Figure 29 may be

combined with any combination or subcombination of the other embodiments that were described above.

Figure 30 is a flowchart of steps that may be performed to package semiconductor light emitting devices according to various embodiments of the present invention. Methods of Figure 30 may be used to package one or more semiconductor light emitting devices, to provide structures that were described in any of the preceding figures.

As shown in Figure 30 at Block **3010**, a solid metal block including cavities and heat sink fins is fabricated, as was described extensively above. An insulating layer is formed on at least a portion of the solid metal block, for example on the first metal face thereof, at Block **3020**, as was described extensively above. At Block **3030**, a conductive layer is formed on the insulating layer. The conductive layer may be patterned to provide a reflective coating in the cavities, and first and second conductive traces on the first face that extend into the cavities, as was described extensively above. At Block **3040**, at least one semiconductor light emitting device is mounted in a respective cavity, and electrically connected to the first and second conductive traces in the respective cavity, as was described extensively above. At Block **3050**, an optical coupling medium may be added, as was described above. At Block **3060**, a lens, optical element and/or flexible film is placed on the first face, as was described extensively above. In other embodiments, through holes, reflector layers and/or other structures that were described extensively above, also may be provided.

It also will be noted that in some alternate implementations, the functions/acts noted in the blocks of Figure 30 may occur out of the order noted in the flowchart. For example, two blocks shown in succession may, in fact, be executed substantially concurrently, or the blocks may sometimes be executed in the reverse order, depending upon the functionality/acts involved.

Additional discussion of various embodiments of the present invention now will be provided. Embodiments of the present invention can provide a three-dimensional topside and backside topology on solid metal blocks, to thereby provide integral reflector cavities and integral heat sinks all in one piece. The integrated optical cavities may facilitate alignment and ease of manufacturing. The integral heat sink may enhance thermal efficiency. By adopting a three-dimensional topside topology to form reflectors for the LEDs, the need to individually package the LEDs,

mount the package to a heat sink and add the desired drive electronics may be eliminated, according to some embodiments of the present invention. Thus, a "chip on integral reflector heat sink" may be provided as a single component. High optical efficiency and high thermal efficiency thereby may be provided. Adding the drive
5 circuitry can provide a complete solution for a functional luminary that may only need a source voltage and a final luminary housing.

Any shape or density device may be provided. For example, one may desire to have a high lumen intensity (lumen per square millimeter), or one may desire to enhance or optimize the thermal efficiency by distributing the cavity layout. A high
10 density embodiment may have four high power LEDs such as are marketed under the designation XB900 by Cree, Inc., the assignee of the present invention, to provide a 2%2 array, while a distributed thermal approach may have 100 lower power LEDs, such as are marketed under the designation XB290 by Cree, Inc., the assignee of the present invention, to provide a 10%10 array, to achieve the same lumen output. The
15 XB900 and XB290 devices are described in a product brochure entitled *Cree Optoelectronics LED Product Line*, Publication CPR3AX, Rev. D, 2001-2002. Other devices that are described in this product brochure, such as XT290, XT230 and/or other devices from other manufacturers also may be used.

As was described above, the optical cavities may be either recessed or may be
20 provided as optical cavities in pedestals. The conductive layer can provide die-attach pads and wire bond pads. Separate traces may be provided for red, green or blue LEDs, or all the LEDs may be connected in series or in parallel.

Embodiments of the present invention can provide a configuration that may be able to replace a standard MR16 or other light fixture. In some embodiments, 6.4
25 watts input may provide about 2.4 watts of optical power and 4 watts of heat dissipation.

Figure 31 illustrates other embodiments of the present invention. As described above in connection with Figures 1A-1H, a mounting substrate for a semiconductor light emitting device includes a solid metal block **100** having a cavity **110** in a first
30 metal face **100a** thereof that is configured to mount a semiconductor light emitting device **150** therein. Cavity **110** may include reflective oblique sidewalls **110a** which reflect light emitted by device **150** and direct the reflected light out of the cavity **110**. An insulating coating **120** is provided on the surface of the metal block **100**. The

semiconductor light emitting device **150** is electrically connected to first and second electrical traces **130a'**, **130b'** which are formed on the insulating coating **120**, and which in the illustrated embodiment extend around at least one side **100c** of the metal block **100** and onto a second face **100b** of the metal block **100** that is opposite the first face **100a**.

As described in connection with other embodiments of the invention, a package for a semiconductor light emitting device may additionally include an optical element such as a lens **170** mounted above the cavity **110**, and the cavity **110** may include, and in some embodiments may be filled with, an encapsulant material **160** such as an epoxy resin or a silicone. In some embodiments, the encapsulant material **160** may include wavelength conversion material such as a phosphor, light scattering elements, and/or other materials.

During manufacturing, the encapsulant material may be injected as a liquid into the cavity **110**. As discussed in U.S. Provisional Patent Application Serial No. 60/557,924 entitled *"Methods For Packaging A Light Emitting Device"* filed March 31, 2004, and U.S. Provisional Patent Application Serial No. 60/558,314 entitled *"Reflector Packages And Methods For Packaging Of A Semiconductor Light Emitting Device"* filed March 31, 2004, the disclosure of each of which is hereby incorporated herein in its entirety as if set forth fully herein, it may be desirable to control the amount of encapsulant material **160** injected into the cavity **110**. Also, manufacturing constraints may make controlling the volume of encapsulant material **160** injected into the cavity **110** difficult, particularly when the cavity **110** is very small. Surface tension in the injected liquid may cause the liquid to form a characteristic meniscus shape. As described in the provisional applications referenced above, this meniscus can be used to assist in controlling the volume of encapsulant material injected and in reducing or preventing squeeze-out of the encapsulant by causing the meniscus to form at desired features on the substrate. Typically, these meniscus control features, which may comprise corners, edges, are formed near the locations at which the lens **170** contacts the package. However, it may be difficult to form the meniscus control features at the edge of the cavity **110** and also to provide electrical traces **130a'**, **130b'** extending from the cavity **110**.

In addition, when the encapsulant **160** contains wavelength conversion material, it may be desirable to inject a predetermined volume of encapsulant material into the cavity **110** in order to obtain desirable wavelength conversion characteristics.

This means that, in some embodiments, the cavity **110** may be quite deep to accommodate the desired volume of encapsulant material **160**. In that case, forming electrical traces **130a'**, **130b'** on the first face **100a** of block **100** as well as the floor **110b** of the cavity **110** may involve printing the electrical traces on two planes
5 separated by a substantial vertical distance, which may present a difficult challenge. Not only may this make the manufacturing process more costly and/or time-consuming, but it may cause line tolerances to be sacrificed in order to form electrical traces on planes that are separated by more than a small distance.

In order to permit the formation of a large-volume cavity for receiving an encapsulant material while maintaining acceptable trace dimensions, some
10 embodiments of the invention include a cover plate **3100** matingly attached to block **100** and including therein an aperture **3110** which extends completely through the cover plate **3100** and is configured to be aligned to cavity **110**. The cover plate **3100**, which may comprise a reflective and/or non-reflective material, may be matingly
15 attached to block **100** using a non-conductive epoxy and/or through other suitable means such as mechanical detents. In some embodiments, the cover plate **3100** may comprise a metal such as aluminum, copper and/or steel. Alternatively, the cover plate **3100** may comprise ceramic or Liquid Crystal Polymer (LCP) plastic. LCP plastic may be engineered to have a coefficient of thermal expansion that is
20 compatible with the block **100** and may also survive the typical processing temperatures that are used to fabricate light emitting device packages.

In some embodiments, it may be desirable to form the cover plate **3100** using a material that has a high heat conductivity, thereby enabling the cover plate **3100** to act as a second heat sink. Moreover, in some embodiments, the heat sink fins **190**
25 need not be present.

Once cover plate **3100** is in place, aperture **3110** creates a second cavity **3120** adjacent the optical cavity **110** that is configured to receive an encapsulant material **160**. In some embodiments, the aperture **3110** includes sidewalls **3110a** which may be vertical and/or oblique. In some embodiments, the sidewalls **3110a** are reflective
30 and may be shaped to enhance and/or optimize the amount and/or direction of light that is reflected away from the second cavity **3120**. Stated differently, the second cavity **3120** may be shaped to extend or enhance the optical characteristics of the cavity **110**. The sidewalls **3110a** of the aperture **3110** may be formed of a reflective material such as aluminum, and/or may be coated with a reflective material.

The cover plate **3100** may further include meniscus control features such as corners **3130a**, **3130b** on which a meniscus **160a** of liquid encapsulant material **160** may be formed. The cover plate **3100** may further include a recess **3140** that is configured to receive a lens **170** therein.

5 An additional potential advantage of the embodiments illustrated in Figure 31 is that the electrical traces on the first face **100a** of block **100** may be covered by the cover plate **3100**. Thus, the electrical traces may be protected from environmental and/or mechanical damage.

10 In some embodiments, the aperture **3110** may include a recess **3150** to define a ledge and expose a portion of the surface **100a** of block **100** on which an electrical trace such as **130a'** is formed to permit the bonding of a contact wire **1650** from the device **150** to the electrical trace such as **130a'**. Moreover, as shown in Figure 31, the first and second electrical traces **130a'**, **130b'** may be defined by patterning on the first face **100a** of the solid metal block **100** rather than in the cavity
15 **110**. The contact wire **1650** then may be bonded to the electrical trace **130a'** on the first face **100a** rather than in the cavity **110**. Patterning on the first face **100a** may simplify manufacturing because the break can be made on a planar surface, and may also increase the amount of reflective material in the cavity **110**.

20 In some embodiments illustrated in Figure 32, the metal block **100** may include a plurality of optical cavities **110**. In these embodiments, the cover plate **3100** likewise includes a plurality of apertures **3110** aligned to cavities **110**.

 It will also be understood that various combinations and subcombinations of embodiments of Figures 31 and/or 32 may be used with Figures 1A-30, according to various embodiments of the present invention. For example, pedestals may be
25 provided. Moreover, multiple caps may be stacked upon one another in some embodiments.

 In the drawings and specification, there have been disclosed embodiments of the invention and, although specific terms are employed, they are used in a generic and descriptive sense only and not for purposes of limitation, the scope of the
30 invention being set forth in the following claims.

What is Claimed is:

1. A mounting substrate for a semiconductor light emitting device comprising:
 - a solid metal block including first and second opposing metal faces;
 - the first metal face including therein a cavity that is configured to mount at
 - 5 least one semiconductor light emitting device therein and to reflect light that is emitted by at least one semiconductor light emitting device that is mounted therein away from the cavity; and
 - a cap including an aperture that extends therethrough, the cap being configured to matingly attach to the solid metal block adjacent the first metal face
 - 10 such that the aperture is aligned to the cavity.
2. A mounting substrate according to Claim 1 further comprising:
 - a plurality of heat sink fins in the second metal face.
- 15 3. A mounting substrate according to Claim 1 further comprising a reflective coating in the cavity and in the aperture.
4. A mounting substrate according to Claim 1 further comprising a first conductive trace on the first metal face and a second conductive trace in the cavity
- 20 that are configured to connect to at least one semiconductor light emitting device that is mounted in the cavity.
5. A mounting substrate according to Claim 1 wherein the first metal face further includes a pedestal therein and wherein the cavity is in the pedestal.
- 25 6. A mounting substrate according to Claim 1 in combination with at least one semiconductor light emitting device that is mounted in the cavity.
7. A mounting substrate according to Claim 6 in further combination with
- 30 a lens that extends across the aperture.
8. A mounting substrate according to Claim 6 wherein the at least one semiconductor light emitting device comprises at least one light emitting diode.

9. A mounting substrate according to Claim 6 in combination with an optical coupling media in the cavity and in the aperture.

5 10. A mounting substrate according to Claim 4 wherein the aperture includes therein a recess that is configured to expose the first conductive trace on the first face.

10 11. A mounting substrate according to Claim 9 wherein the cover plate includes at least one meniscus control region therein that is configured to control a meniscus of the optical coupling media in the cavity.

12. A mounting substrate for semiconductor light emitting devices comprising:
15 a solid metal block including first and second opposing metal faces;
the first metal face including therein a plurality of cavities, a respective one of which is configured to mount at least one semiconductor light emitting device therein and to reflect light that is emitted by the at least one semiconductor light emitting device that is mounted therein away from the respective cavity; and
20 a cap including a plurality of apertures that extend therethrough, the cap being configured to matingly attach to the solid metal block adjacent the first metal face such that a respective aperture is aligned to a respective cavity.

25 13. A mounting substrate according to Claim 12 further comprising:
a plurality of heat sink fins in the second metal face.

14. A mounting substrate according to Claim 12 further comprising a reflective coating in the plurality of cavities and in the plurality of apertures.

30 15. A mounting substrate according to Claim 12 further comprising first conductive metal traces on the first metal face and second conductive traces in the plurality of cavities that are configured to connect to at least one semiconductor light emitting device that is mounted in the respective cavity.

16. A mounting substrate according to Claim 12 wherein the first metal face further includes a plurality of pedestals therein and wherein a respective one of the plurality of cavities is in a respective one of the plurality of pedestals.

5 17. A mounting substrate according to Claim 12 in combination with at least one semiconductor light emitting device that is mounted in a respective cavity.

18. A mounting substrate according to Claim 17 in further combination with a plurality of lenses, a respective one of which extends across a respective one of
10 the apertures.

19. A mounting substrate according to Claim 17 wherein the semiconductor light emitting devices comprise light emitting diodes.

15 20. A mounting substrate according to Claim 17 in combination with an optical coupling media in the cavities and in the apertures.

21. A mounting substrate according to Claim 15 wherein a respective aperture includes therein a respective recess that is configured to expose the
20 respective first conductive traces on the first face.

22. A mounting substrate according to Claim 17 wherein the cover plate includes a plurality of meniscus control regions therein that are configured to control a meniscus of the optical coupling media in the respective cavity.

25 23. A semiconductor light emitting device packaging method comprising:
fabricating a solid metal block including first and second opposing metal faces, the first metal face including therein a plurality of cavities, a respective one of which is configured to mount at least one semiconductor light emitting device therein
30 and to reflect light that is emitted by the at least one semiconductor light emitting device that is mounted therein away from the respective cavity;

forming an insulating layer on the first metal face;

forming a conductive layer on the insulating layer that is patterned to provide a reflective coating in the plurality of cavities, first conductive traces on the first face

and second conductive traces in the plurality of cavities that are configured to connect to a plurality of semiconductor light emitting devices that are mounted in the cavities;

mounting at least one semiconductor light emitting device in a respective cavity, and electrically connected to the first and second conductive traces; and

5 matingly attaching to the solid metal block adjacent the first metal face, a cap including a plurality of apertures that extend therethrough, such that a respective aperture is aligned to a respective cavity.

10 24. A method according to Claim 23 wherein mounting is preceded by:
fabricating a reflective coating in the plurality of cavities.

25. A method according to Claim 23 wherein matingly attaching is followed by:

15 placing an optical coupling media in the cavities and in the apertures.

26. A method according to Claim 25 wherein placing an optical coupling media is followed by:

placing a respective lens across a respective one of the apertures.

20 27. A semiconductor light emitting device package comprising:
a solid metal block including first and second opposing metal faces, the first metal face including therein a plurality of cavities, a respective one of which is configured to mount at least one semiconductor light emitting device therein and to reflect light that is emitted by the at least one semiconductor light emitting device that
25 is mounted therein away from the respective cavity;

an insulating layer on the first metal face;

at least one semiconductor light emitting device in a respective cavity;

30 a conductive layer on the insulating layer that is patterned to provide a reflective coating in the plurality of cavities, first conductive traces on the first face and second conductive traces in the plurality of cavities that electrically connect to the at least one semiconductor light emitting device in the respective cavity; and

a cap that is matingly attached to the solid metal block adjacent the first face, the cap including a plurality of apertures that extend therethrough that are affixed such that a respective aperture is aligned to a respective cavity.

28. A package according to Claim 27 further comprising optical coupling media in the cavities and in the apertures.

- 5 29. A package according to Claim 28 further comprising:
a plurality of lenses, a respective one of which extends across a respective one of the apertures.

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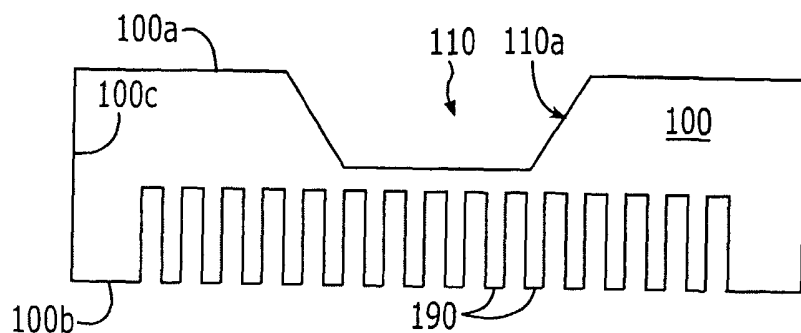


FIG. 1A

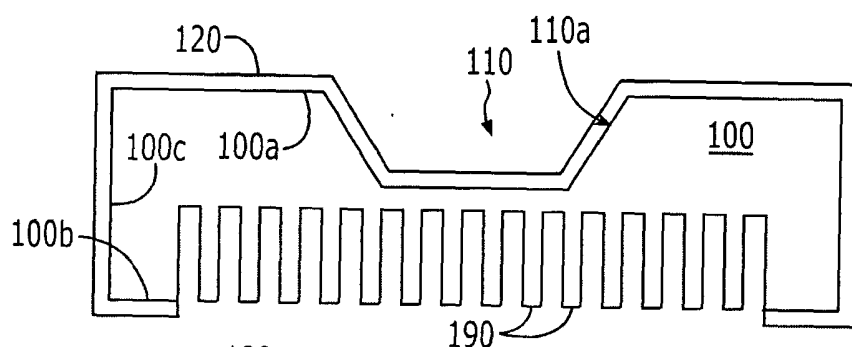


FIG. 1B

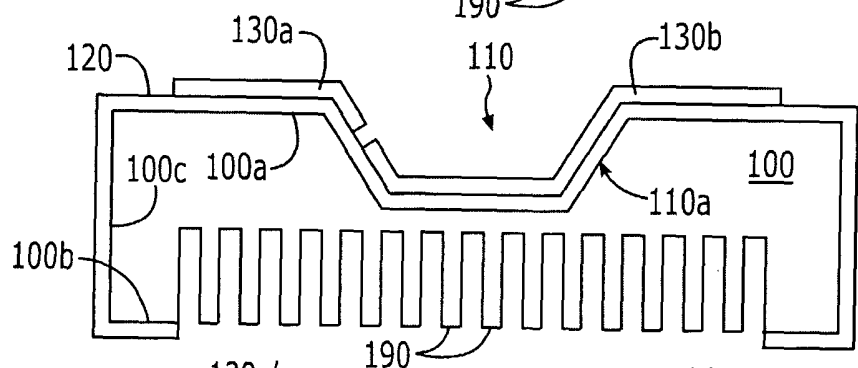


FIG. 1C

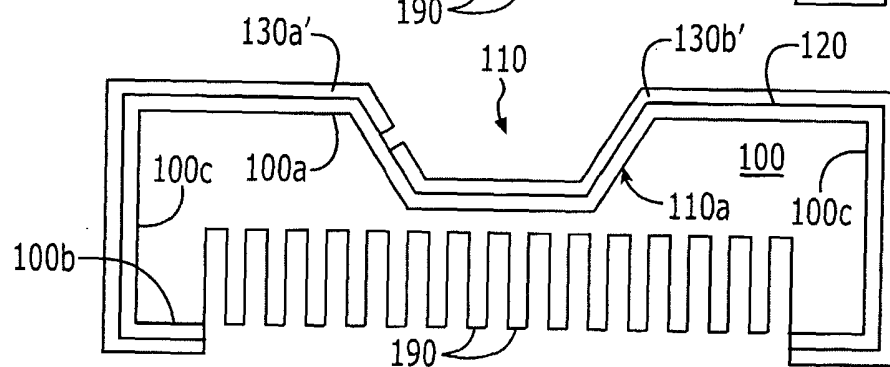


FIG. 1D

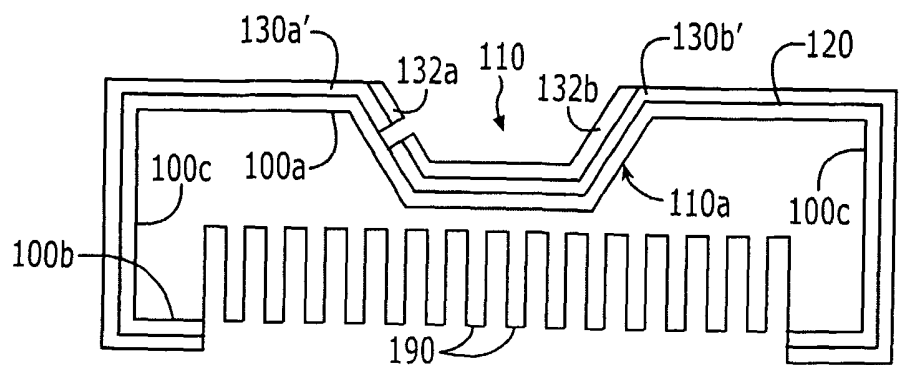


FIG. 1E

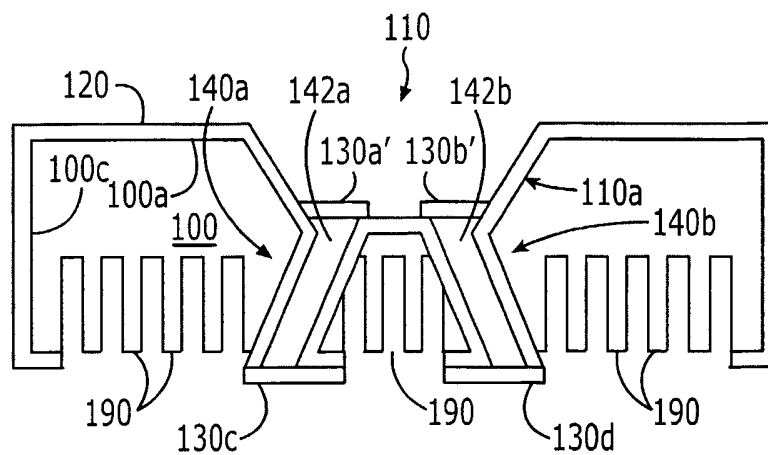


FIG. 1F

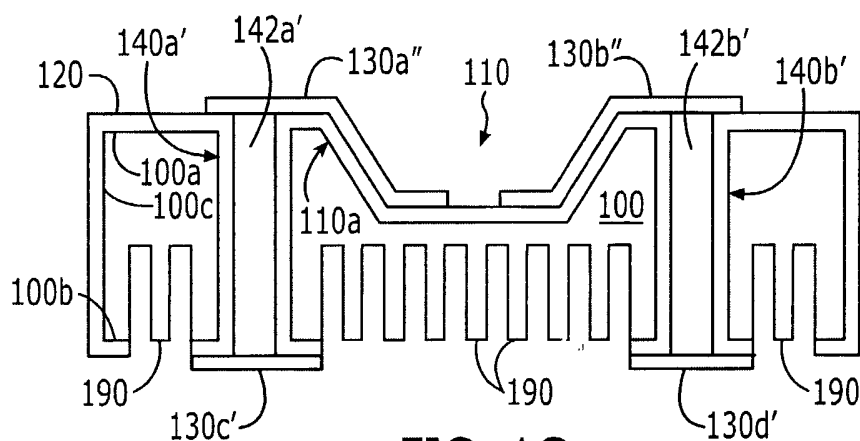


FIG. 1G

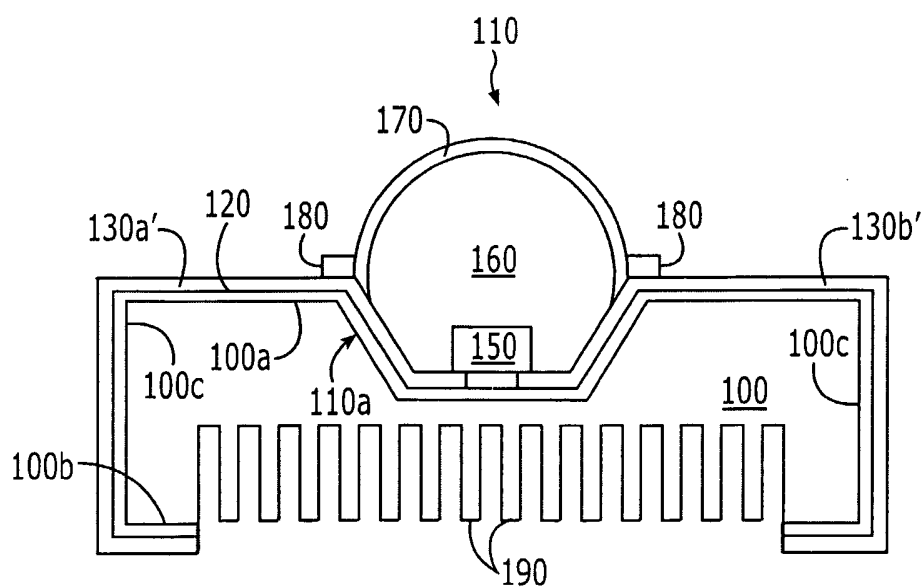
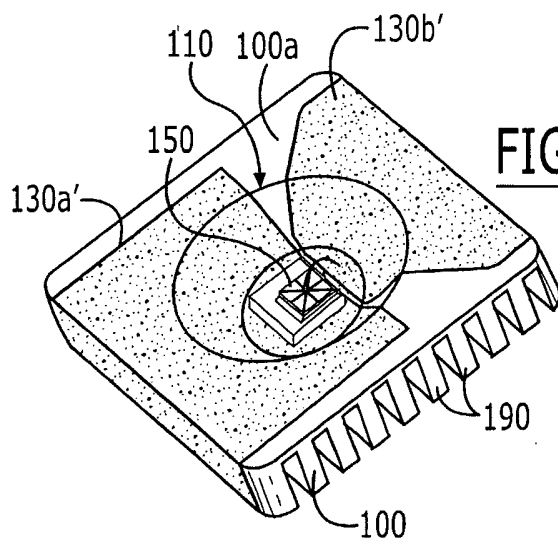
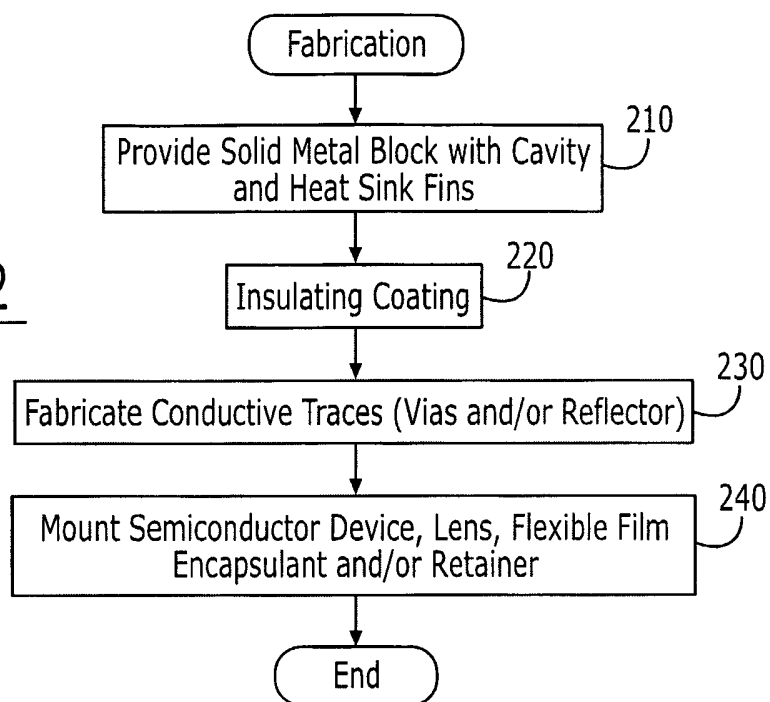
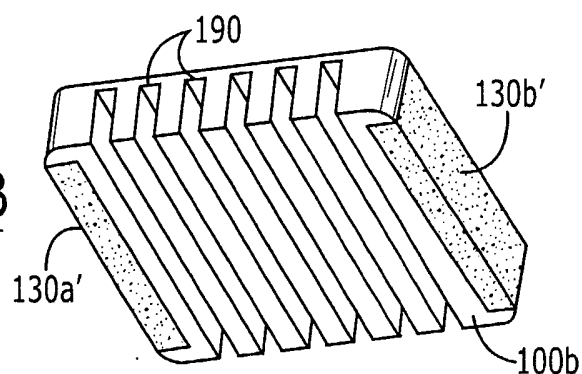
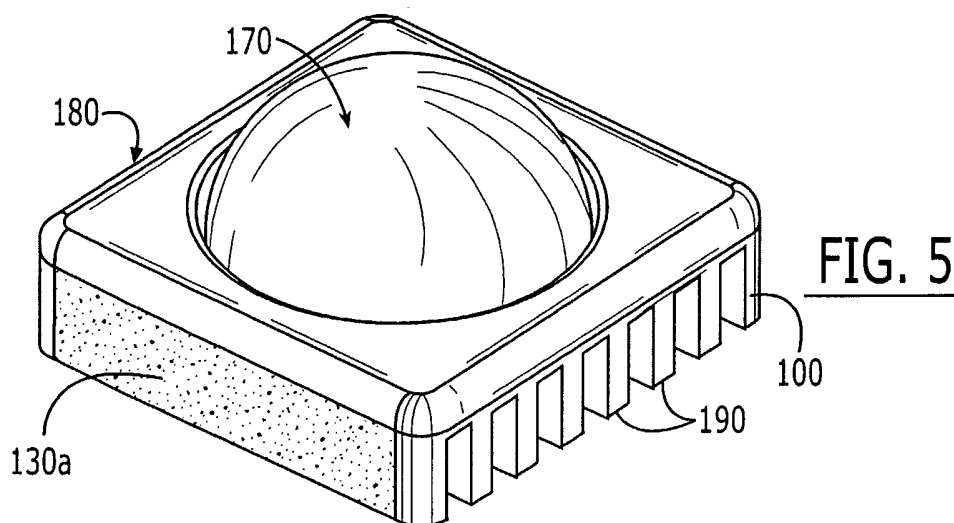
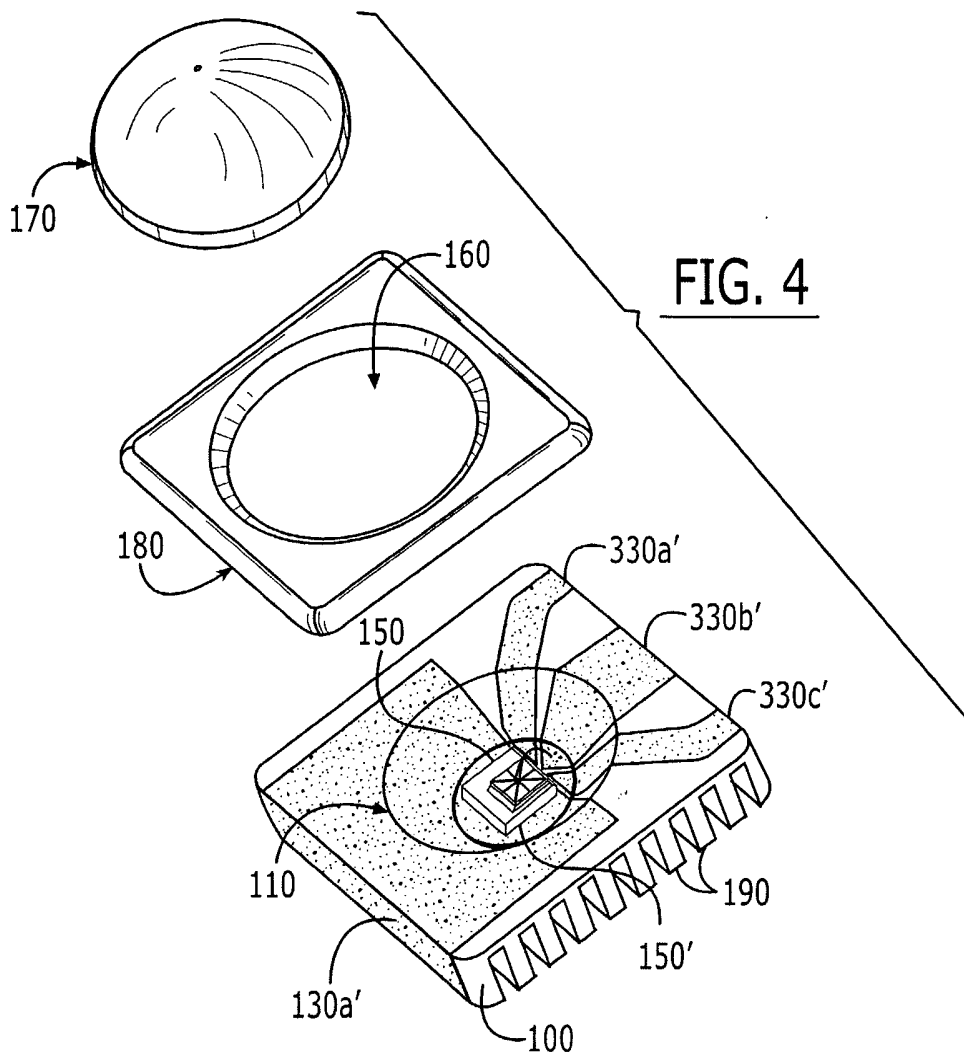


FIG. 1H

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FIG. 2FIG. 3AFIG. 3B

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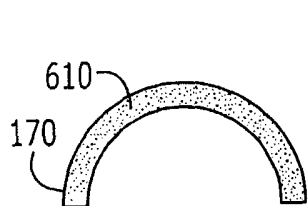


FIG. 6A

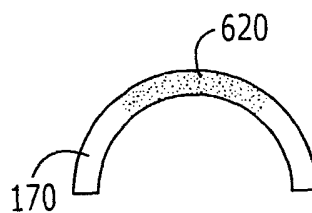


FIG. 6B

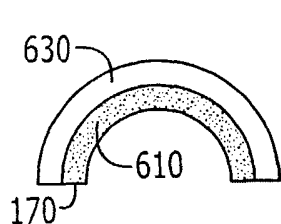


FIG. 6C

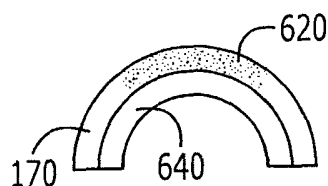


FIG. 6D

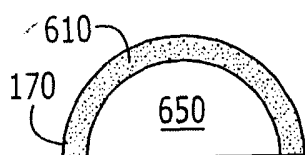


FIG. 6E

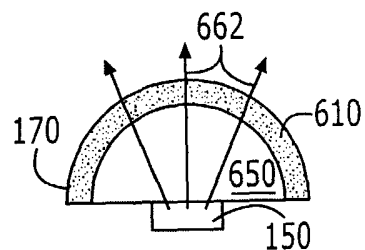


FIG. 6F

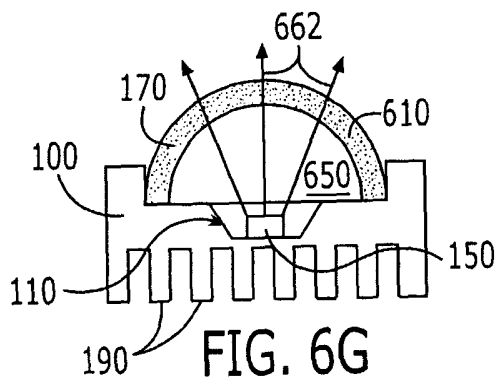


FIG. 6G

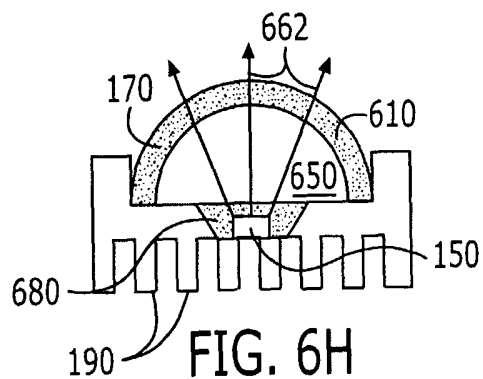


FIG. 6H

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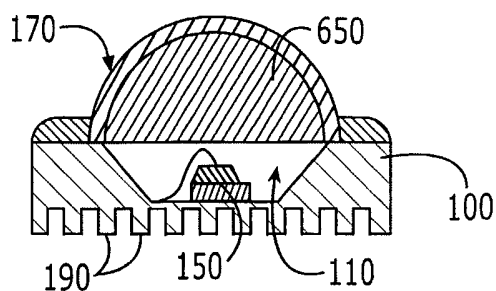


FIG. 7

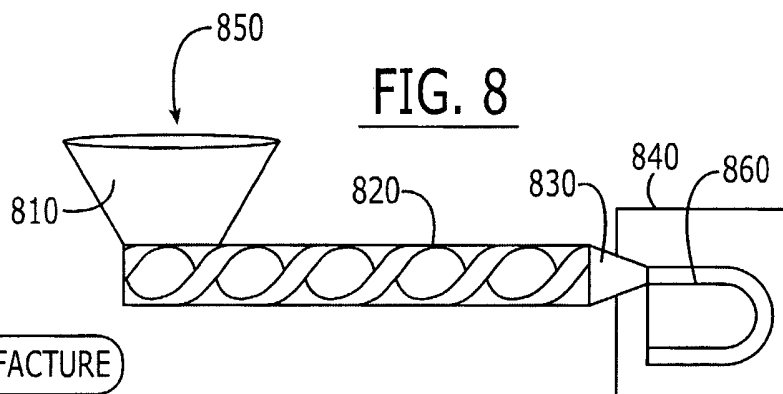


FIG. 8

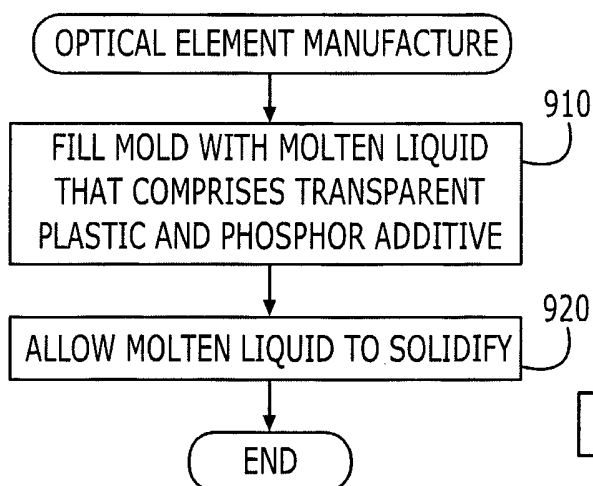


FIG. 9

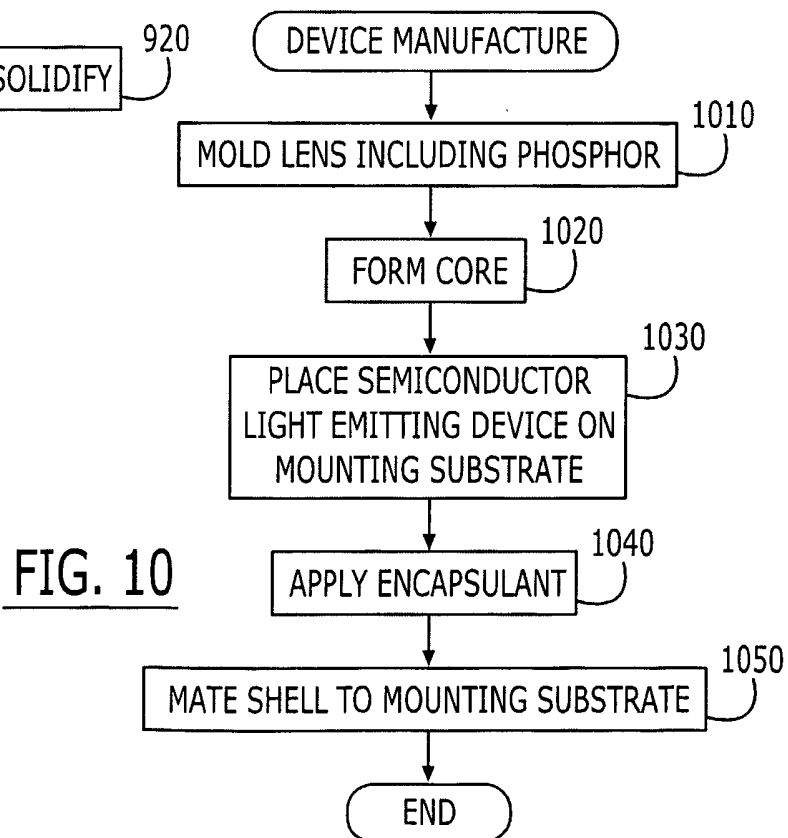
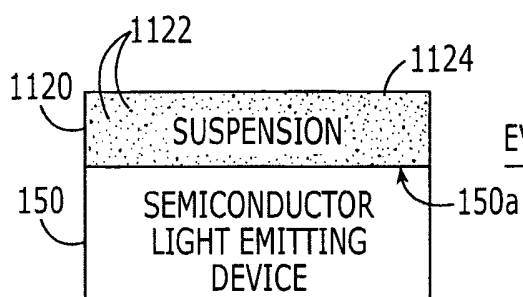
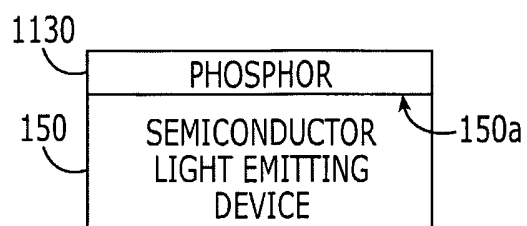
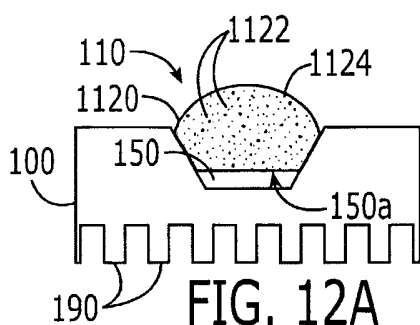


FIG. 10

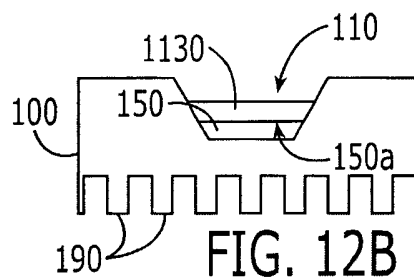
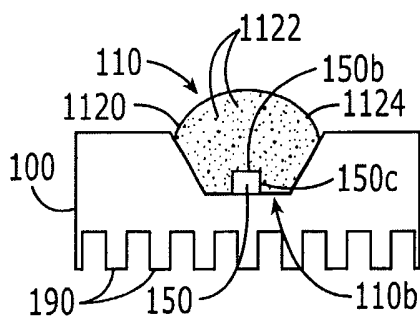
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FIG. 11A

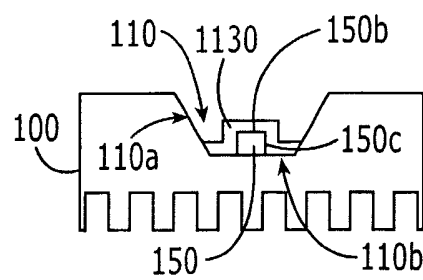
EVAPORATE

FIG. 11BFIG. 12A

EVAPORATE

FIG. 12BFIG. 13A

EVAPORATE

FIG. 13B

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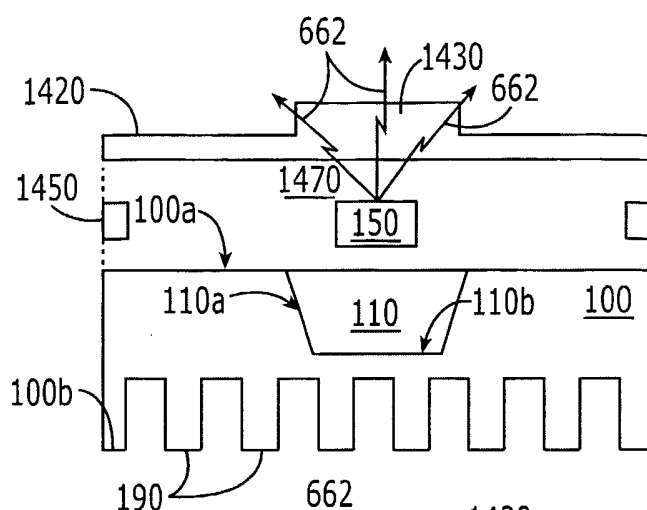


FIG. 14

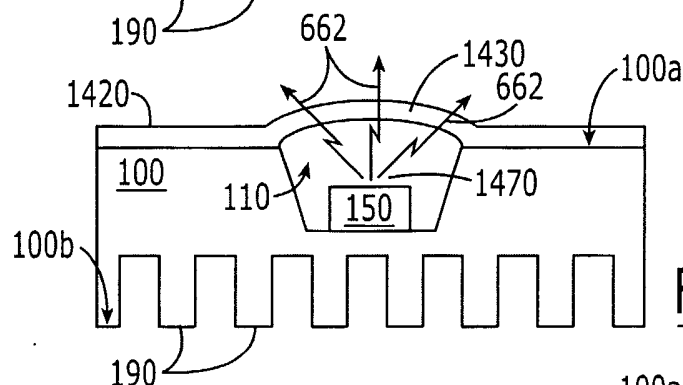


FIG. 15

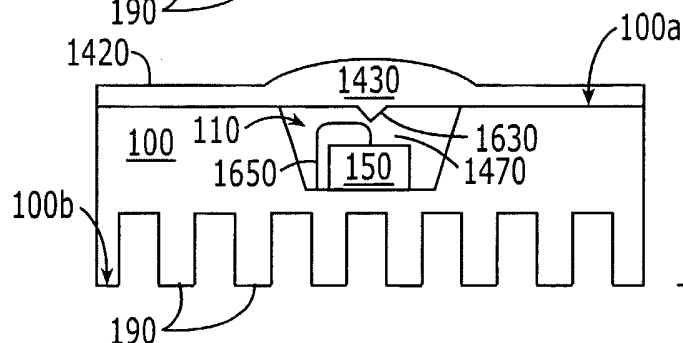


FIG. 16

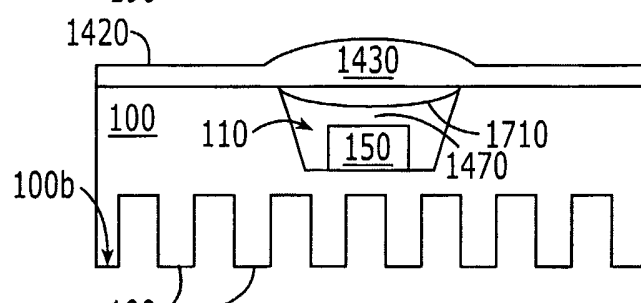


FIG. 17

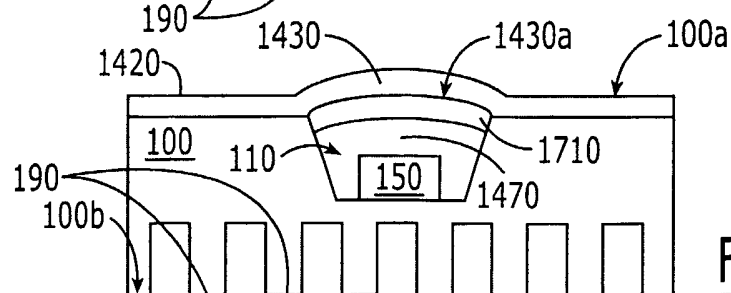


FIG. 18

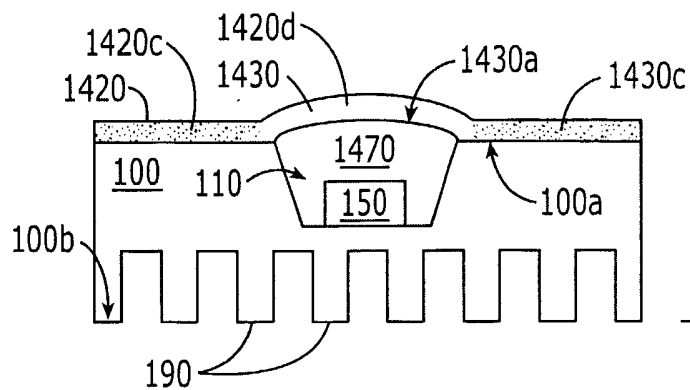


FIG. 19

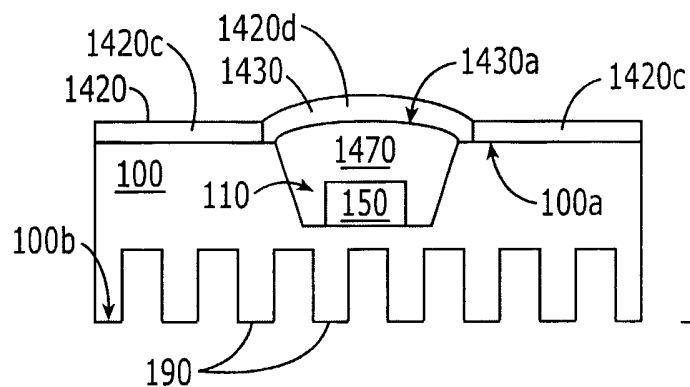


FIG. 20

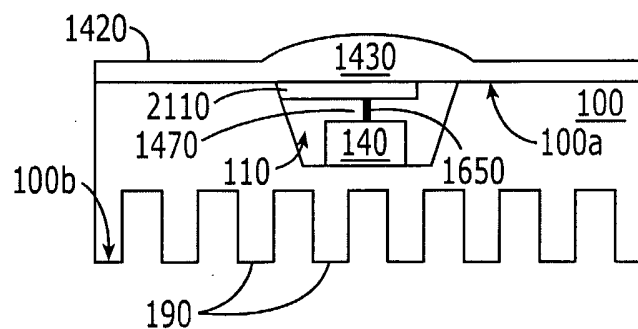


FIG. 21

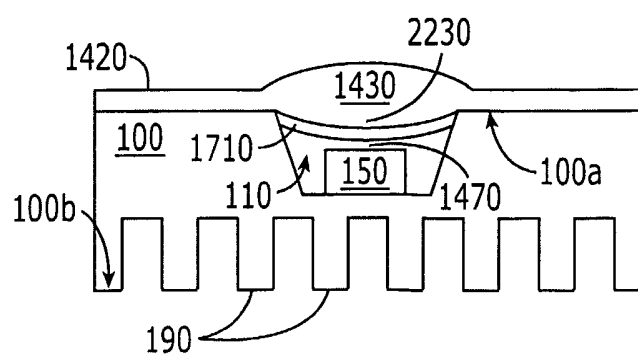


FIG. 22

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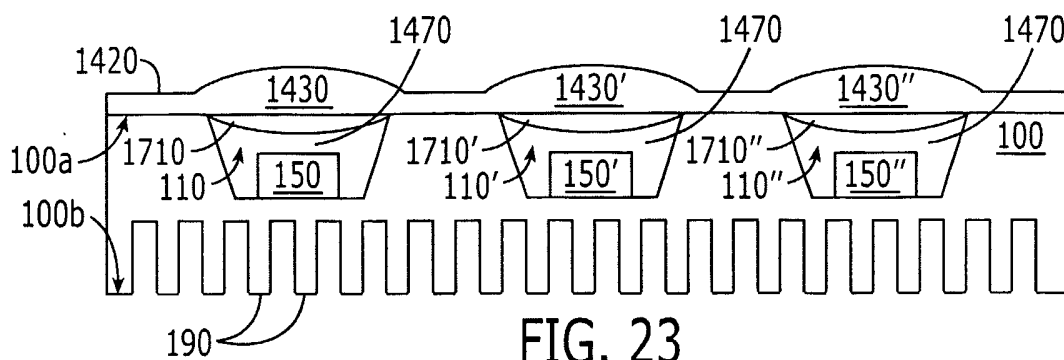


FIG. 23

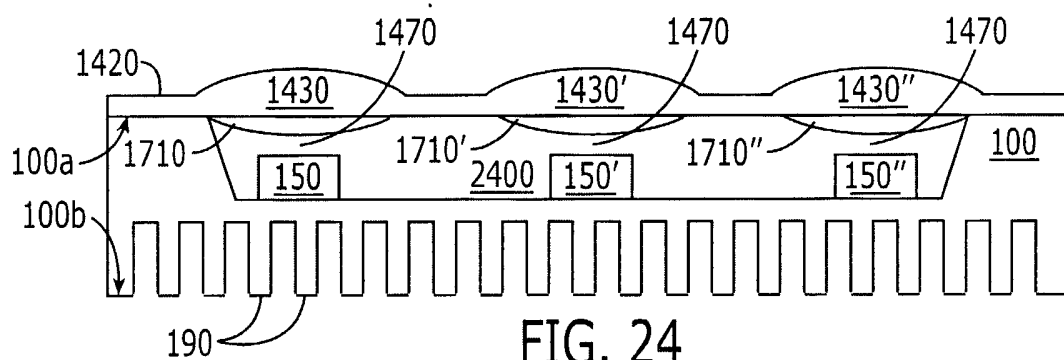


FIG. 24

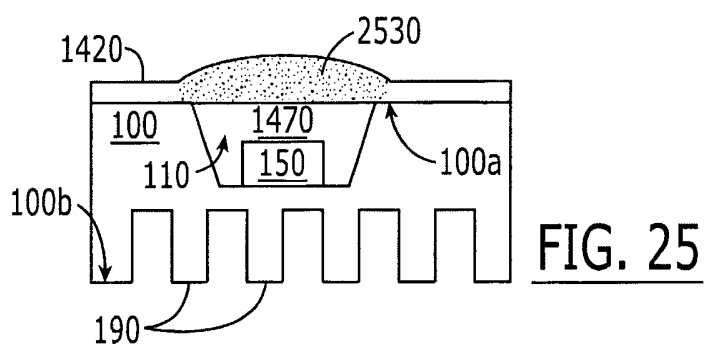


FIG. 25

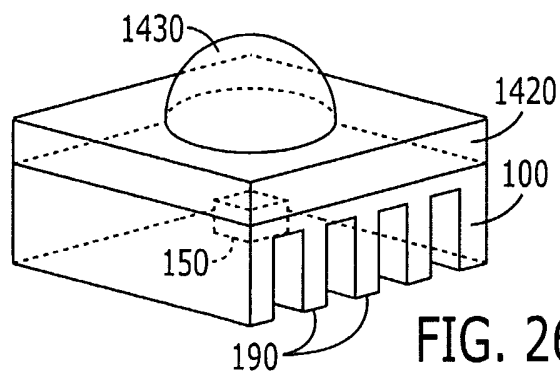


FIG. 26

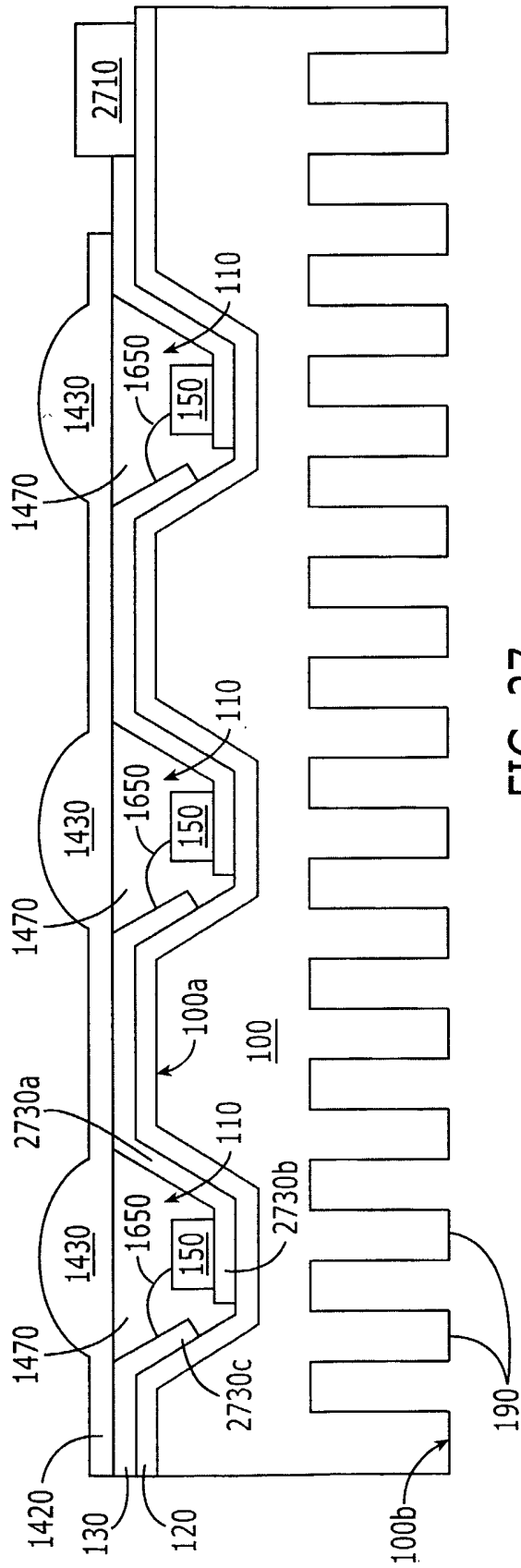
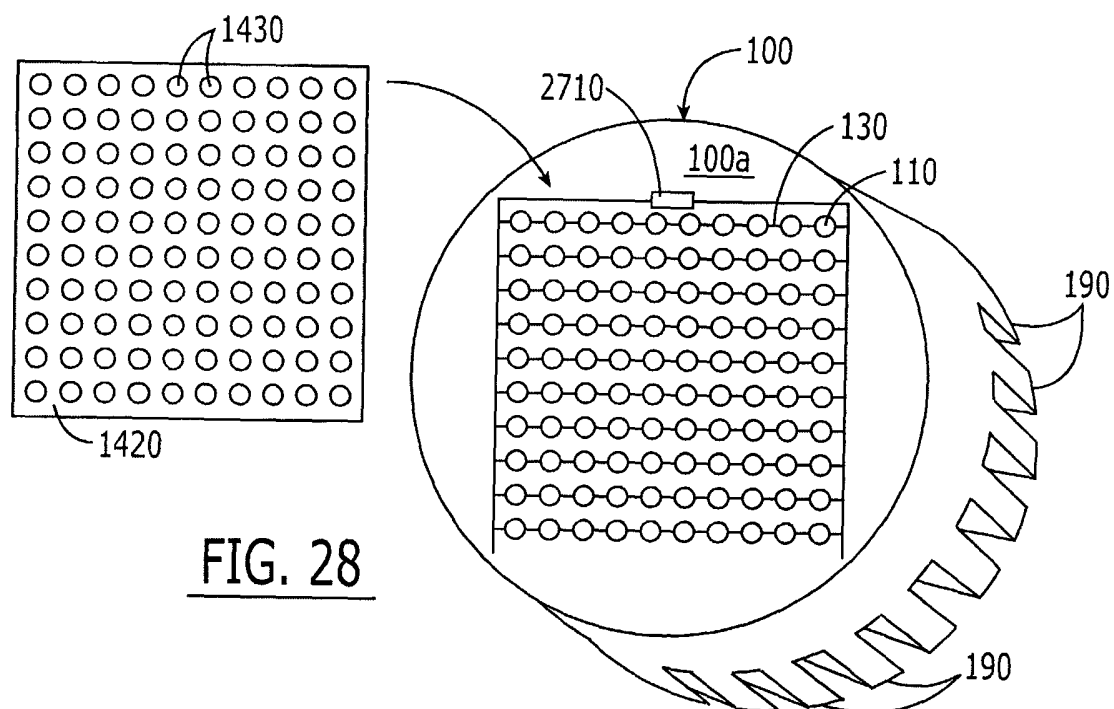


FIG. 27

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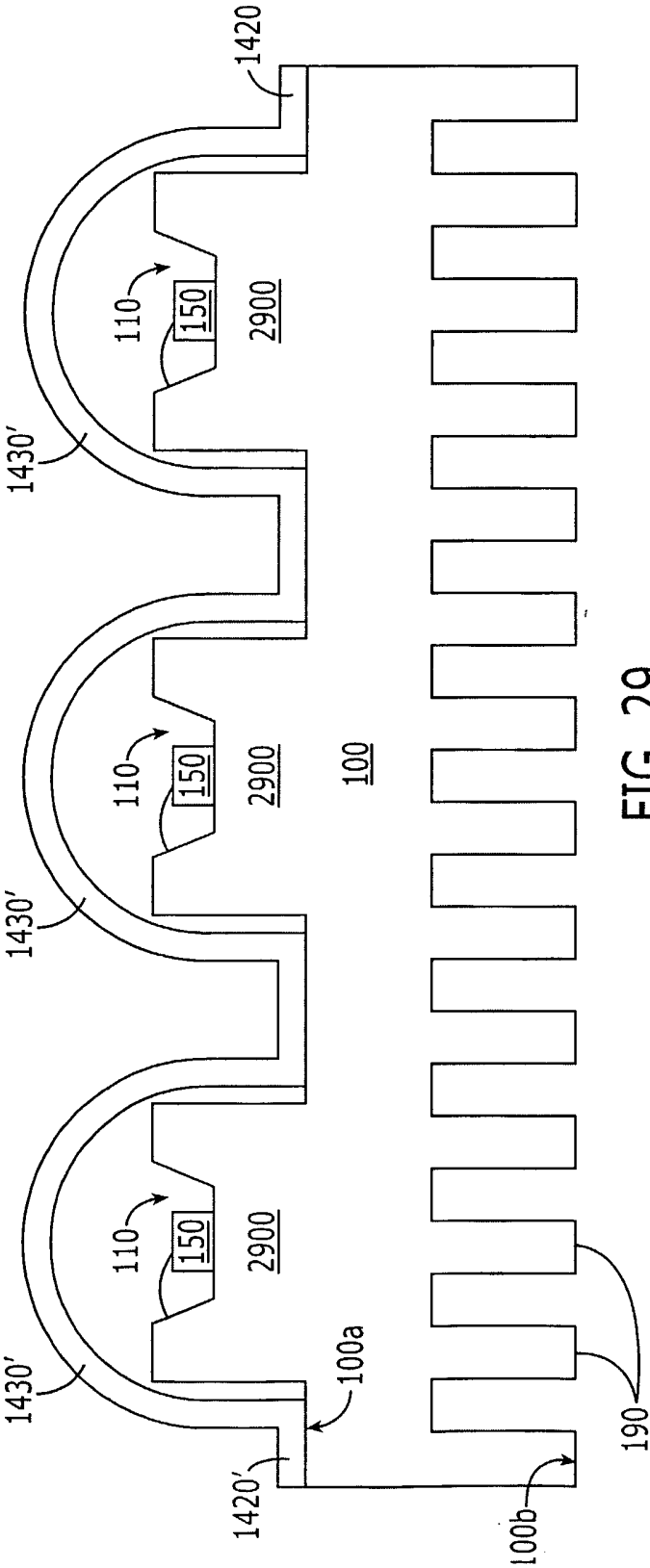
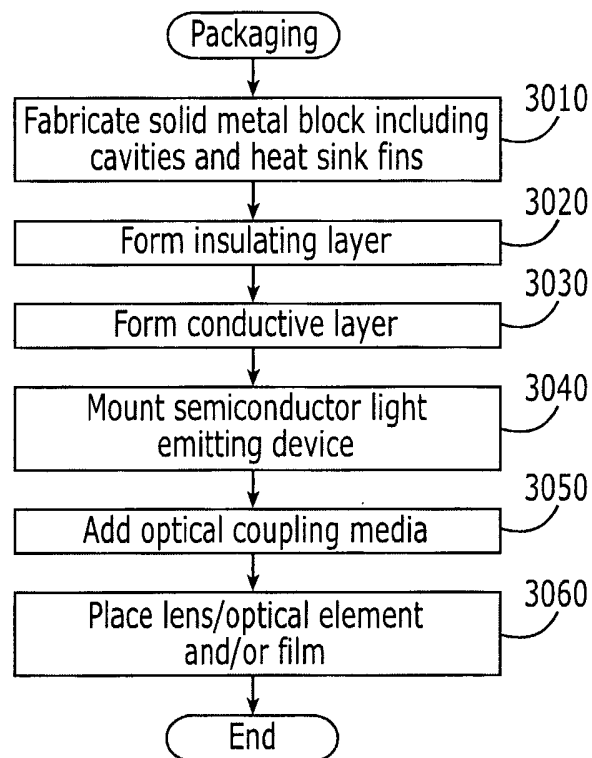
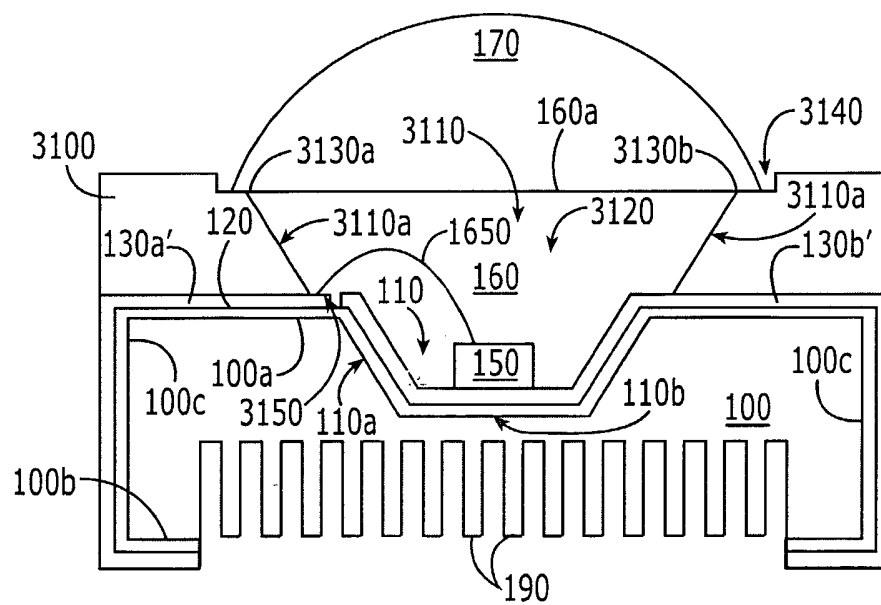


FIG. 29

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FIG. 30

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FIG. 31

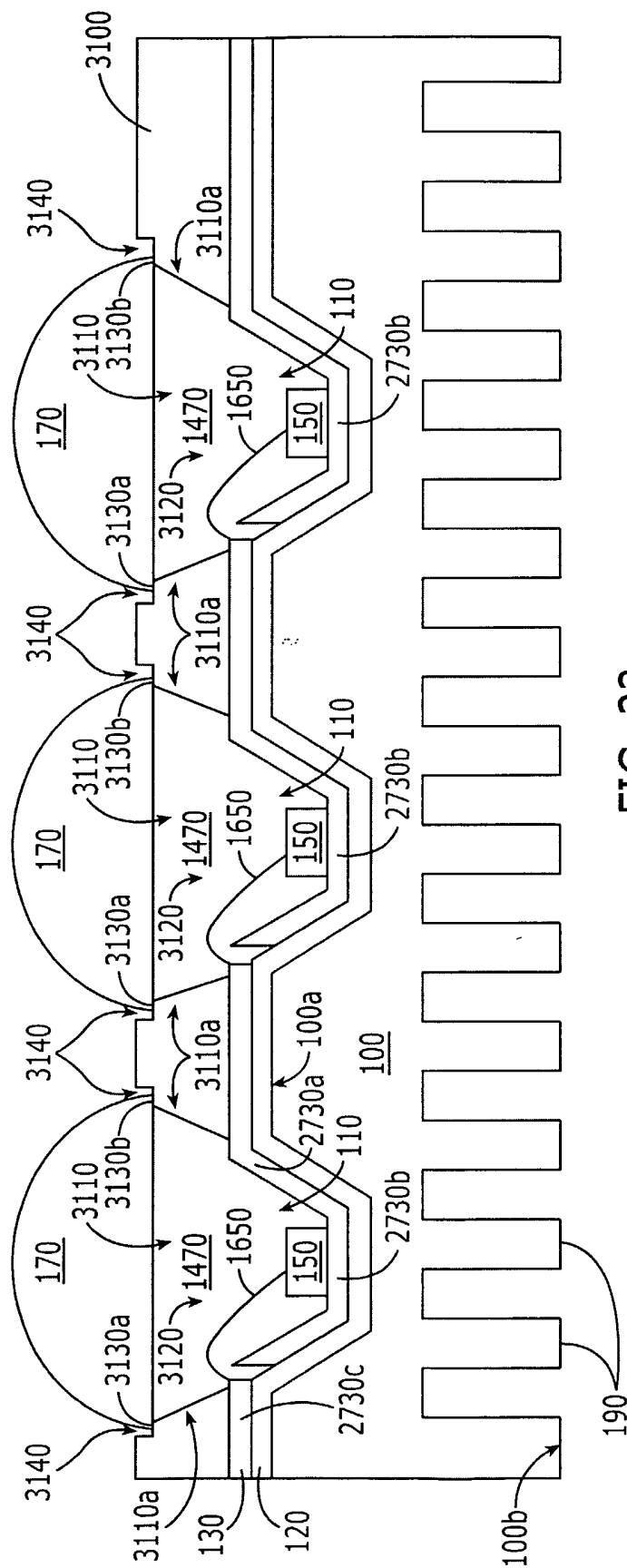


FIG. 32